

Passivating contacts based on thin-film silicon and alloys

Mathieu Boccard

Advancing PV: from passivation to contacts – A passivating contact workshop

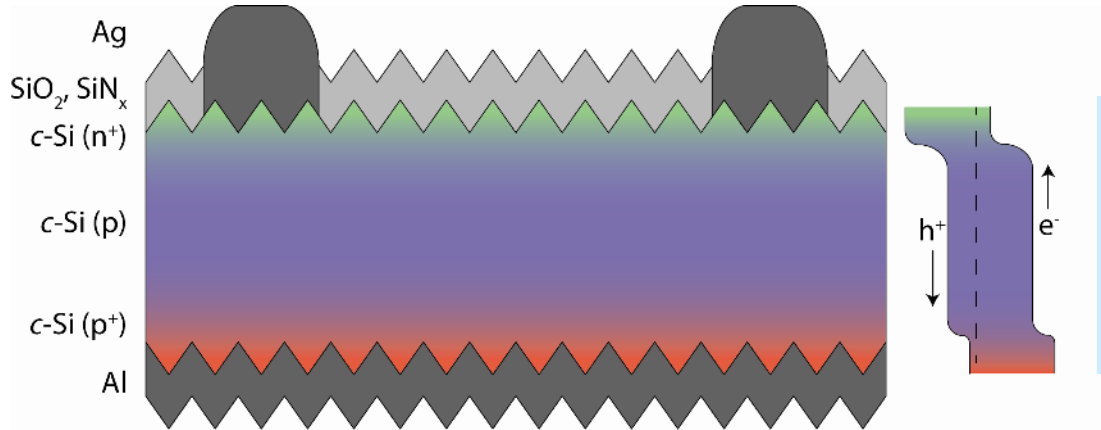
Eindhoven, the Netherlands – 31 January 2017

Heterojunctions based on a-Si:H

- Quick review of HIT solar cells
- Physics of a-Si:H
- Passivation from i-aSi layers and alloys
- Device properties and limitations
- Specific devices and opportunities

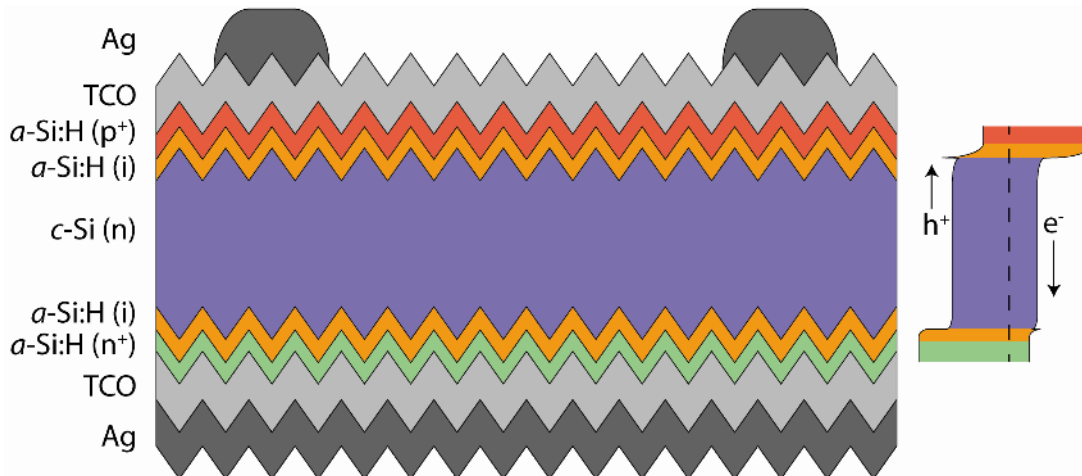
From homo- to heterojunction solar cell

Diffused junction solar cell



Direct contact between
absorber and metal
=
Recombinative contact
→ Lower V_{oc}

Heterojunction solar cell



Thin semiconductor layer **between**
absorber and metal
=
Passivated contact
→ Higher V_{oc}

Process flow

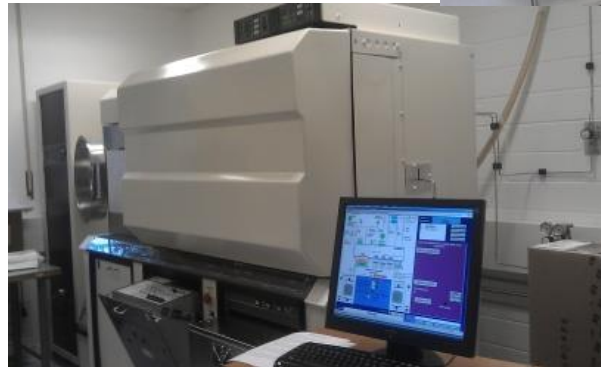
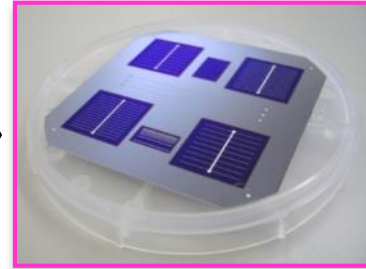
Chemical
baths
c-Si surface
preparation

PECVD I
Intrinsic
film
deposition
a-Si:H(i)

PECVD II
Doped film
deposition
a-Si:H(n/p)

PVD
TCO
sputtering

Metallization
Screen
printing
and curing
at 200° C



Jpn. J. Appl. Phys. Vol. 31 (1992) pp. 3518–3522
Part 1, No. 11, November 1992

Development of New a-Si/c-Si Heterojunction Solar Cells: ACJ-HIT (Artificially Constructed Junction- Heterojunction with Intrinsic Thin-Layer)

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Toru SAWADA, Shinya TSUDA, Shoichi NAKANO,
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(Received July 25, 1992; accepted for publication September 19, 1992)

A new type of a-Si/c-Si heterojunction solar cell, called the HIT (Heterojunction with Intrinsic Thin-layer) solar cell, has been developed based on ACJ (Artificially Constructed Junction) technology. A conversion efficiency of more than 18% has been achieved, which is the highest ever value for solar cells in which the junction was fabricated at a low temperature (<200°C).

KEYWORDS: solar cells, heterojunction, crystalline silicon, amorphous silicon, plasma CVD

Invented by Sanyo (now Panasonic), about 25 years ago... → 18% already !

Commercialized under 'HIT' name shortly after

Heterojunction c-Si technology: record

IEC60904-3Ed.2 101.8cm² (total area) WXS-220S-20

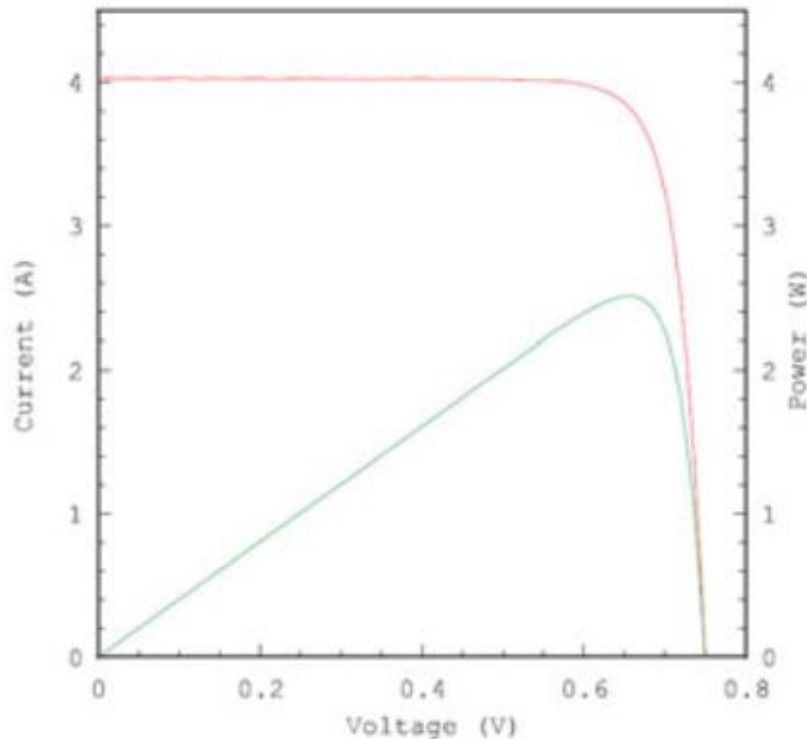
Date : 10 Dec 2012

Data No :

C-11-01

Sample No :

C-11



Efficiency [%]	24.7
J_{sc} [mA/cm ²]	39.5
V_{oc} [mV]	750
FF [%]	83.2
P_{max} [W]	2.510
Total cell area [cm ²]	101.8
Cell thickness [μm]	98

125.83 [mA at 100mW/cm²]

Scan Mode

Isc to Voc



M. Taguchi *et al*, IEEE Journal of Photovoltaics 4(1), 2014, 96-99

→ Highest ever measured V_{oc} on any c-Si solar cell!

Becoming a mainstream technology ?

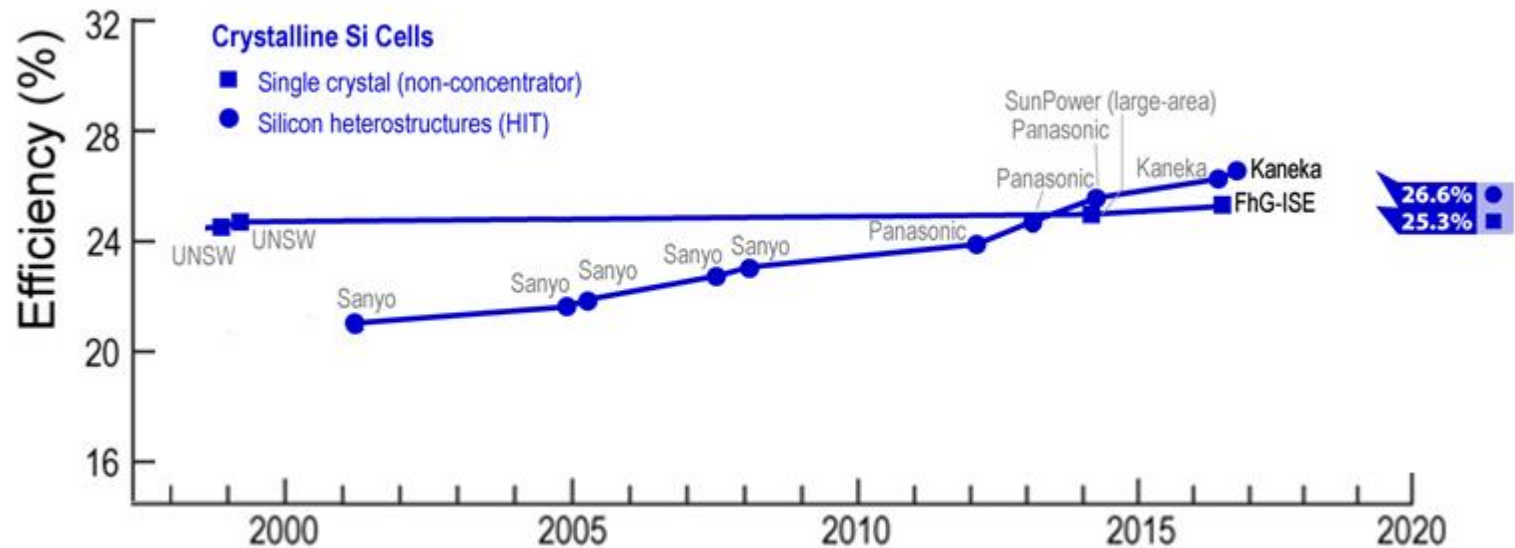
Affiliation	η (%)	V_{oc} (mV)	J_{sc} (mA.cm ⁻²)	FF (%)	A (cm ²)	Status	Year
Panasonic, ¹²⁷ Japan	24.7	750	39.5	83.2	101.8, Cz	IC (AIST)	2013
Kaneka, ¹²⁸ Japan	23.5	737	39.97	79.77	~220, Cz	IC (ISE)	2012
CIC, ¹²⁹ Japan	22.3	733	37.28	81.8	243, Cz	-	2013
CEA-INES, ¹³⁰ France	22.2	730	38.7	78.5	104	IC (ISE)	2012
EPFL, ¹³¹ Switzerland	22.1	726	38.9	78.4	4, FZ	IC (ISE)	2012
RRR, ¹¹⁶ Switzerland	21.9	735	38.5	77.5	4, Cz	-	2011
AUO, ¹³² Taiwan	21.7				6inch		2013
Silevo, ¹³³ US	21.4	729	37.3	78.7		IC	2012
Hyundai HI, ¹³⁴ Korea	21.1	721	36.6	79.9	~220	-	2011
SERIS, ¹³⁵ Singapore	21.1	702.2	38.2	78.6	1	-	2012
AMAT, ¹³⁶ US	>21	>720	>37	>77	149, Cz		2012
Titech, ¹³⁷ Japan	20.1						2012
Samsung, ¹³⁸ Korea	20.14	709	36.51	77.8	154.9	IC (ISE)	2012
HZB, ¹³⁹ Germany	19.8	639	39.3	78.9	1, FZ	IC	2006
OM&T, ¹⁴⁰ the Netherlands	19.7				1		2012
NTUST, ¹⁴¹ Taiwan	19.6	690	39.1	72.7	1, FZ	PR	2011
ISFH, ¹⁴² Germany	19.4	703.7	36	76.5	4	PR	2012
Univ. Hagen, ¹⁴³ Germany	19.3	675	37	77.3	FZ	IC	2009
NREL, ¹⁴⁴ USA	19.24	683.2	36.2	77.7	0.9, Cz	IC	2012
Delft Univ., ¹⁴⁵ the Netherlands	19.0	-	-	-	-	-	2012
AU, ¹⁴⁶ Taiwan	18.9				5 inch		2012
FhG-ISE, ¹⁴⁷ Germany	18.7	~705	~35.0	~75	4, FZ	-	2010
IEC, ⁶⁹ USA	18.3	694	35.7	74.2	0.55, Cz	IC	2008
LG, ¹⁴⁸ Korea	18.2	687	33.3	78.9	1, FZ	-	2010
AIST, ¹⁴⁹ Japan	17.5	656	35.6	75	0.2	PR	2009
Sungkyunkwan Univ., ¹⁵⁰ Korea	17.4	631	36.3	76.1	Cz	PR	2011
LPICM, ¹⁵¹ France	17.2	701	30.8	79.6	4	-	2011
Utrecht Univ., ¹⁵² the Netherlands	16.7	681	33.5	73.1	1 FZ	-	2011
CNR-IMM, ¹⁵³ Italy	16.2	573	36.6	77	1, Cz	-	2005
Univ. Toronto, ¹⁵⁴ Canada	15.5	679	31.7	72.4	4.2, FZ	-	2011
Kyung Hee Univ., ¹⁵⁵ Korea	14	575	34.4	71	Cz	PR	2011
ECN, ¹⁵⁶ the Netherlands	13.2	635	29.1	72	21, FZ	-	2010
KIER, ¹⁵⁷ Korea	12.8	< 600			Cz	-	2009
ENEA, ¹⁵⁸ Italy	12.4	526	31.9	74	mc	-	2010
UPC, ¹⁹⁵ Spain	10.9	525	28.6	72.8	FZ	PR	2006

Increase R&D activities.

Several groups and industries above 20% with screen-printing or plated contacts (CIC, INES/EDF, Kaneka, R&R, LG, Hyundai,.....)

But industries leaving the field, saturation of progress...

Evolution of efficiency

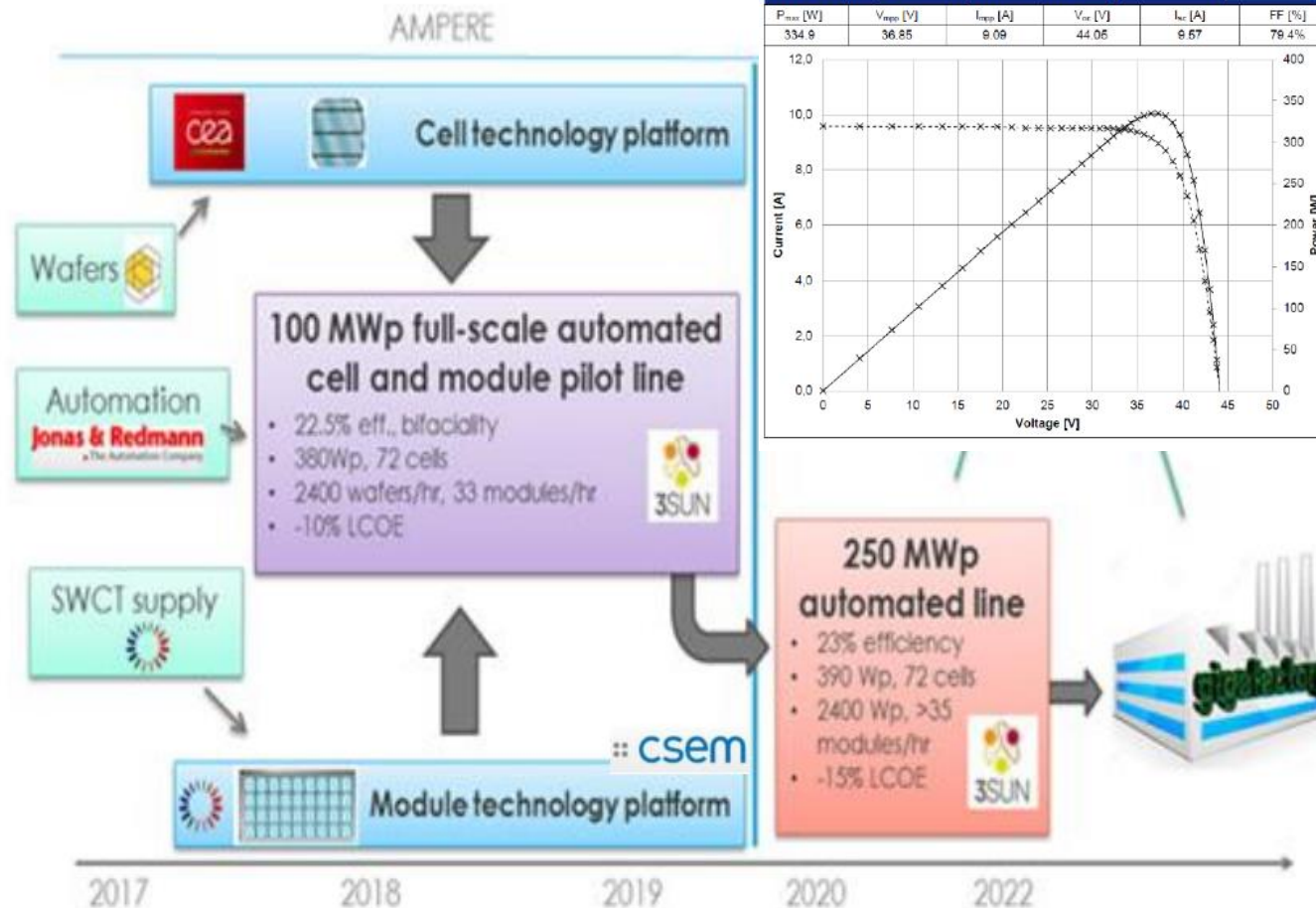


Adapted from <https://www.nrel.gov/pv/assets/images/efficiency-chart.png>
This plot is courtesy of the National Renewable Energy Laboratory, Golden, CO.

Impressive steadiness in the efficiency increase
up to the “practical limit” of Si PV technology...

Becoming a mainstream technology ?

AMPERE: Methodology and Timeline



SHJ module production in Europe !

First demonstration of PECVD a-Si:H (1969)

The Preparation and Properties of Amorphous Silicon

R. C. Chittick, J. H. Alexander, and H. F. Sterling

Standard Telecommunication Laboratories Limited, Harlow, Essex, England

- Resistivity up to $10^{14} \Omega \cdot \text{cm}$
- Large activation energy
- Photoconductivity observed

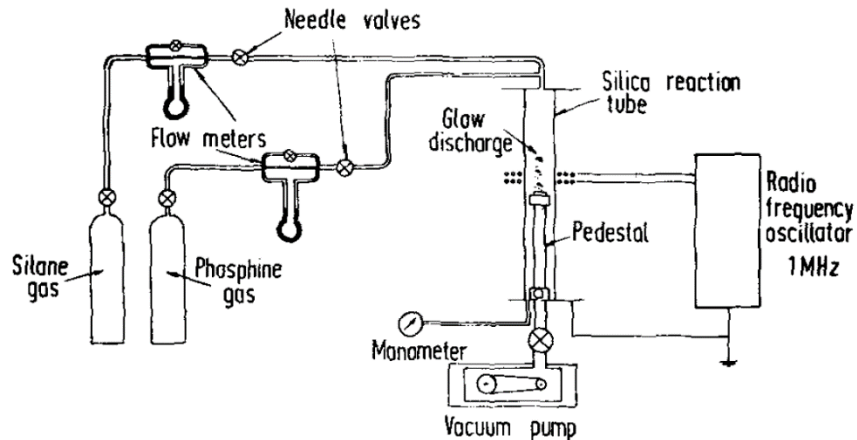


Fig. 1. Glow discharge deposition apparatus

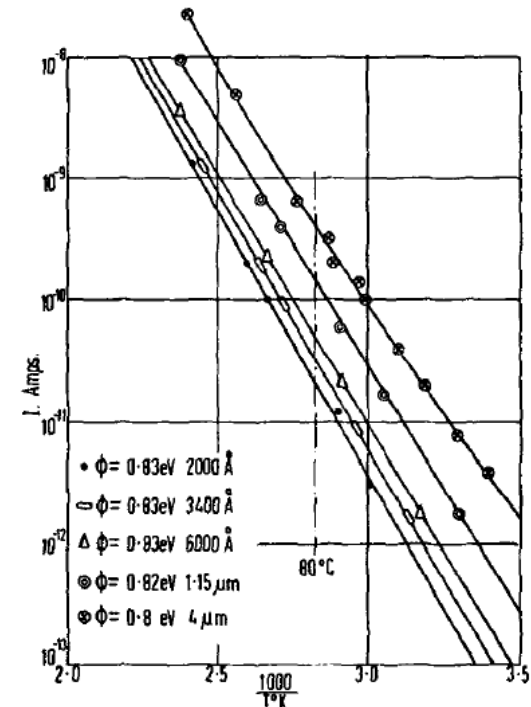
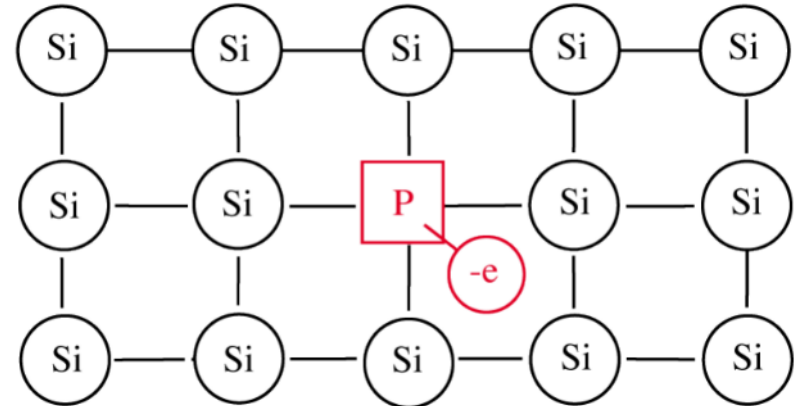
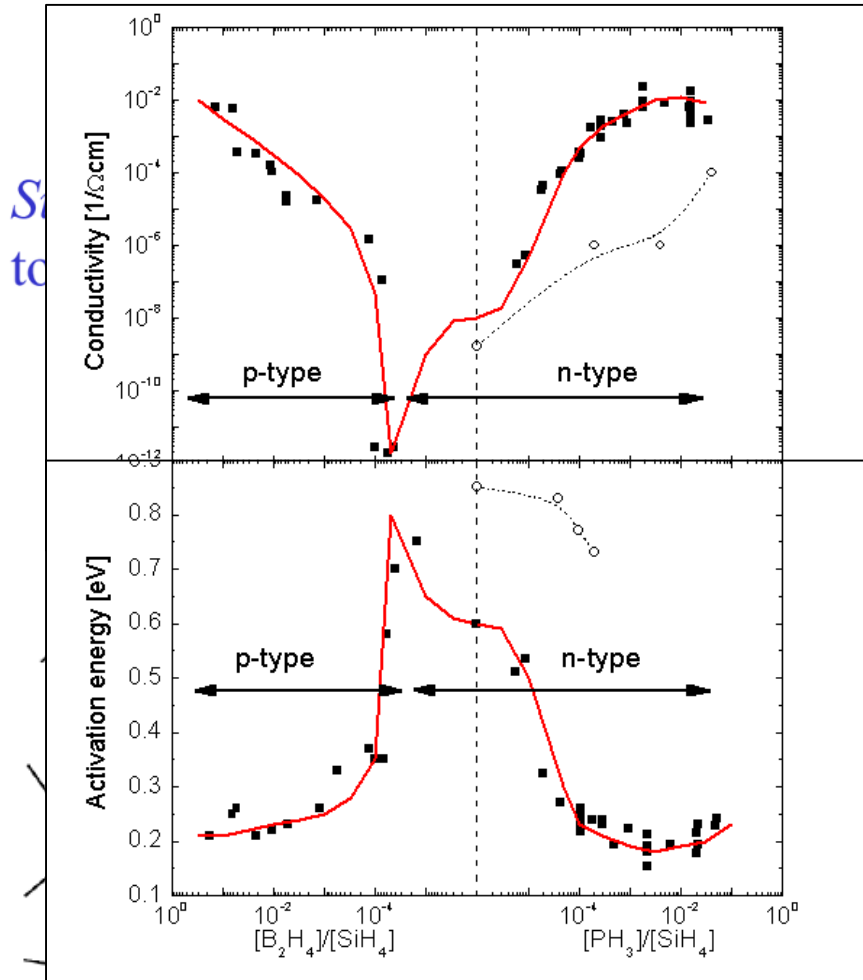


Fig. 2. Deposition temperature 21°C ; variation of electrical conduction with temperature for various thicknesses.

Doping in a-Si:H



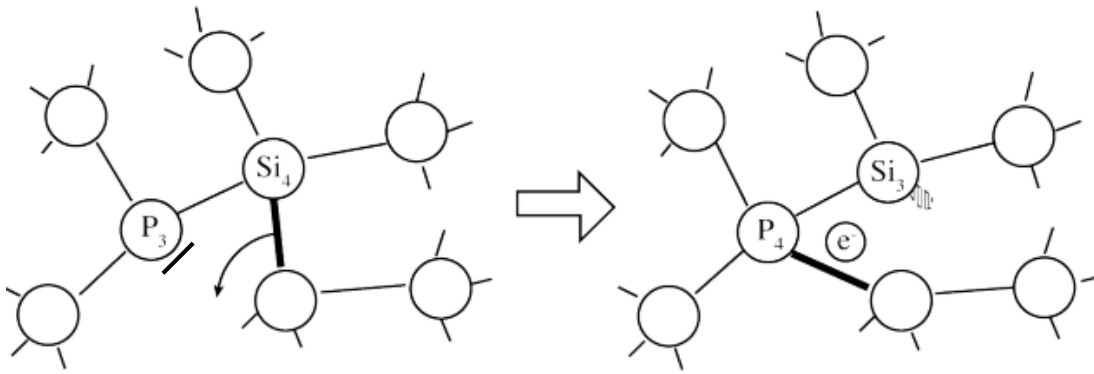
Hydrogenated Amorphous silicon

Doping possible

[9] W. E. Spear and P. G. Lecomber, Substitutional doping of amorphous silicon, *Solid State Communications*, vol. 17, pp. 1193-1196, 1975.

Doping in a-Si:H (1975)

Model of valence transfer :



Transfer of an electron from a weak Si bond on a phosphorous atom will become tetra-coordinated (*donnor effect from the fifth P electron*). This doping effect is correlated with the formation of a *dangling bond* in a neighboring silicon atom.

Substitutional doping and defect creation appears strongly correlated

Doping in a-Si:H (1975)

Experimental tests of the autocompensation model of doping

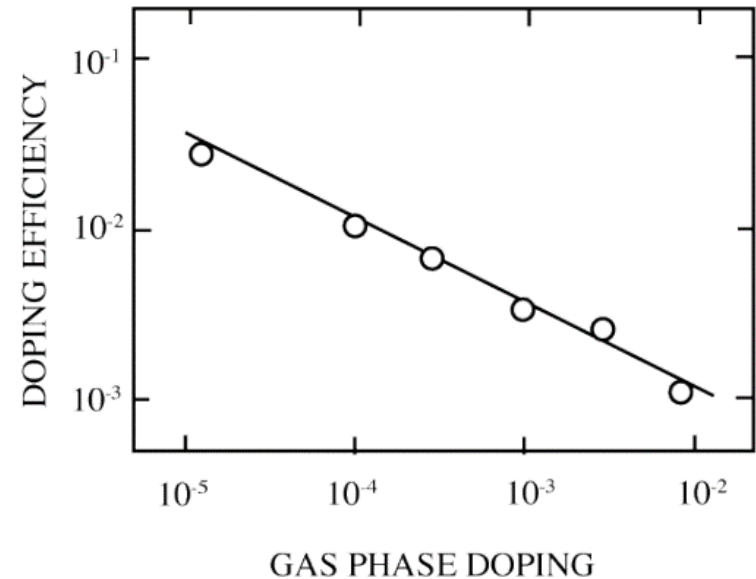
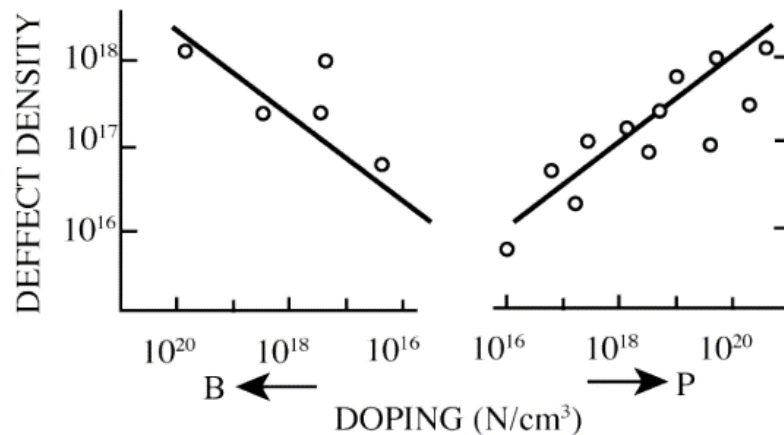
By G. KRÖTZ, J. WIND, H. STITZL, G. MÜLLER

Messerschmitt-Bölkow-Blohm G.m.b.H., Postfach 80 11 09,
8000 München 80, F.R. Germany

S. KALBITZER

Max-Planck-Institut für Kernphysik, Postfach 10 39 80,
6900 Heidelberg, F.R. Germany

and H. MANNSPERGER



Doping possible but at the cost of huge amount of defects... quality too low for p-n solar cells

First cell (1976)

Amorphous silicon solar cell

D. E. Carlson and C. R. Wronski

RCA Laboratories, Princeton, New Jersey 08540
(Received 6 February 1976)

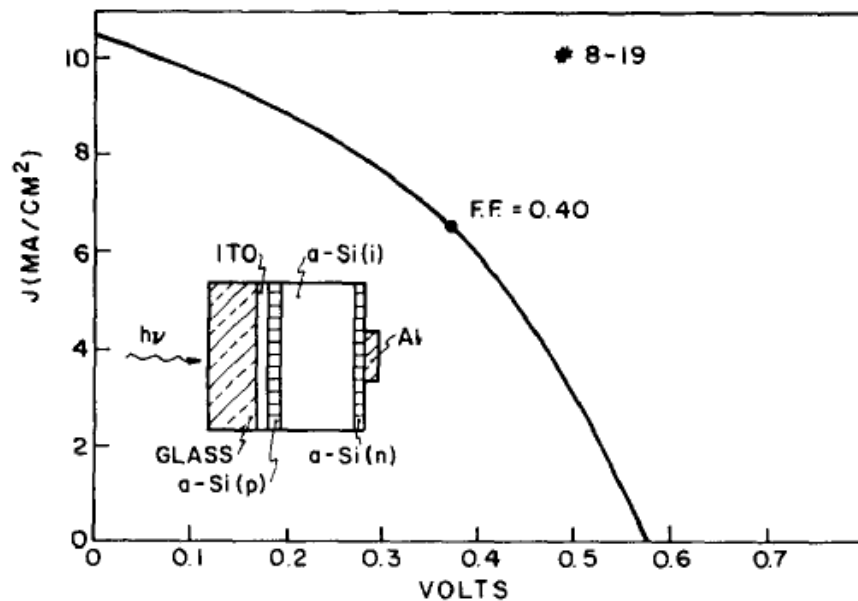


FIG. 1. Current-voltage curve for device #8-19 under illumination comparable to AM-1 sunlight. Also included in the figure is a schematic diagram of a *p-i-n* structure.

With a *p-i-n* structure a solar cell can be made

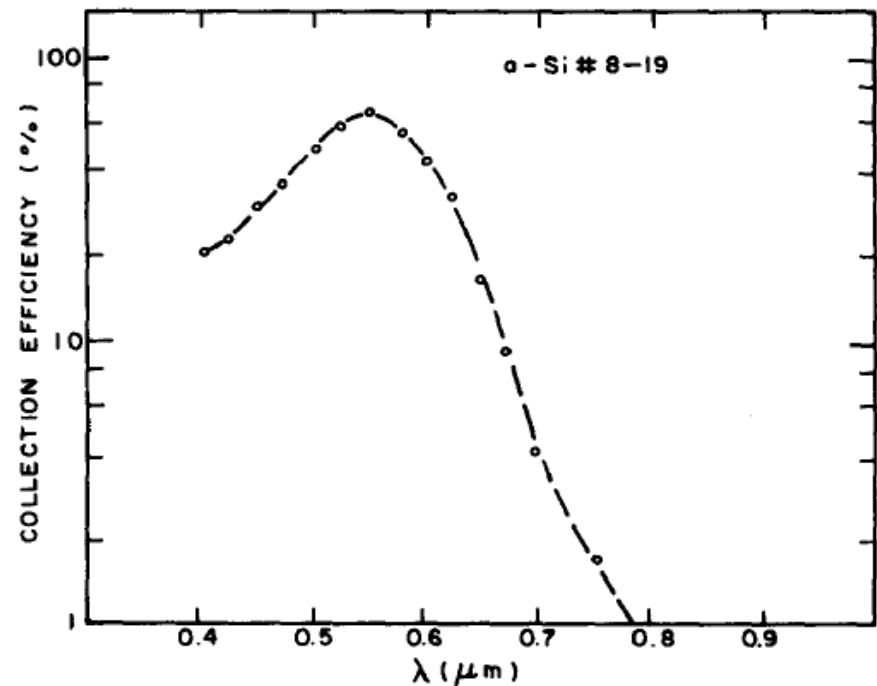


FIG. 2. Collection efficiency as a function of wavelength for device #8-19.

Process fabrication: Si layers

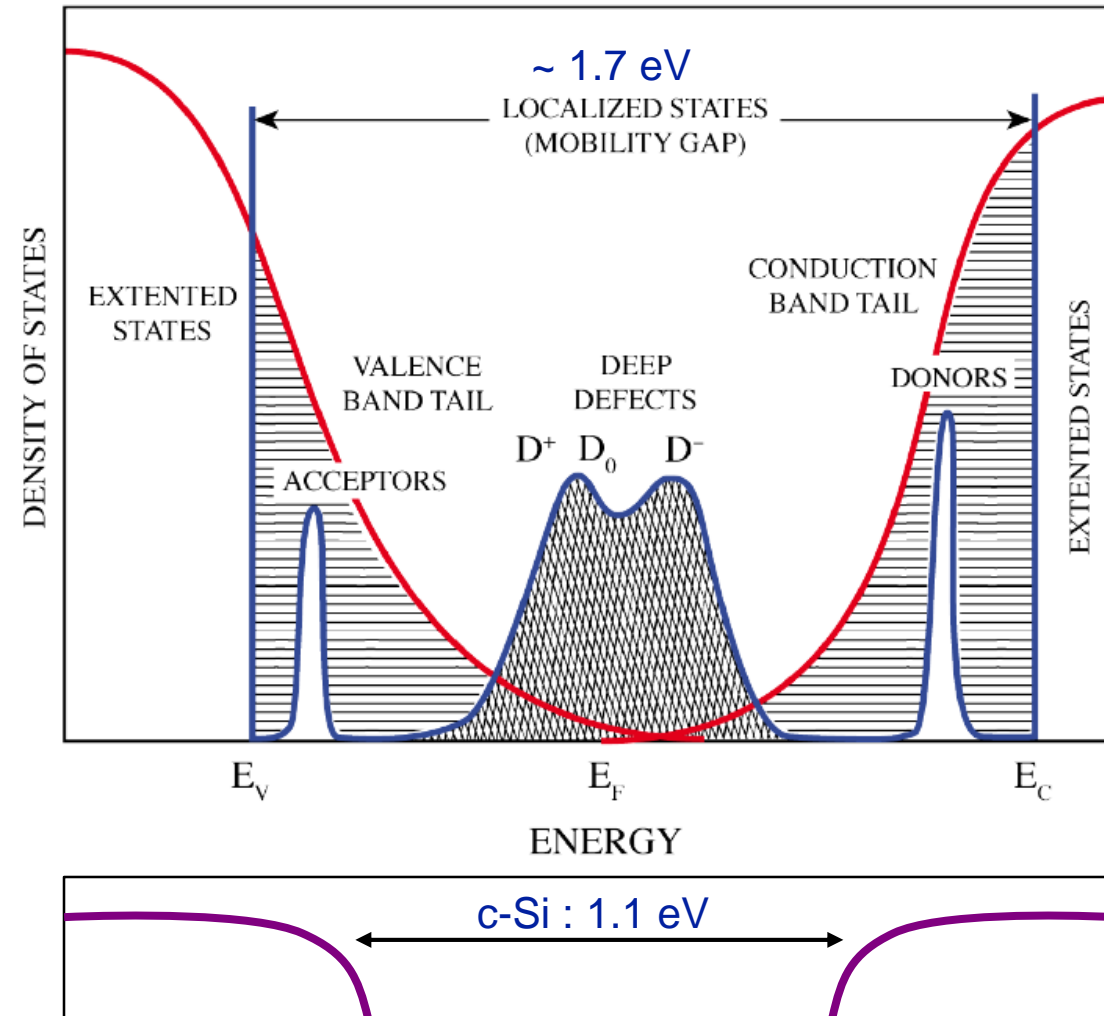


- Millions of square meters of thin-film Si modules,
- TFTs in many displays,



Now mostly consumer electronics...

Typical density of state in a-Si:H



- Band tails (disorder)
- Localized states in the band gap (disorder)
- Increase of deep defect density with doping
- Metastability effects

Material quality limits the efficiency of single-junction a-Si:H cells

Light-induced degradation of a-Si:H (1977)

Reversible conductivity changes in discharge-produced amorphous Si^{a)}

D. L. Staebler and C. R. Wronski

RCA Laboratories, Princeton, New Jersey 08540

(Received 9 May 1977; accepted for publication 17 June 1977)

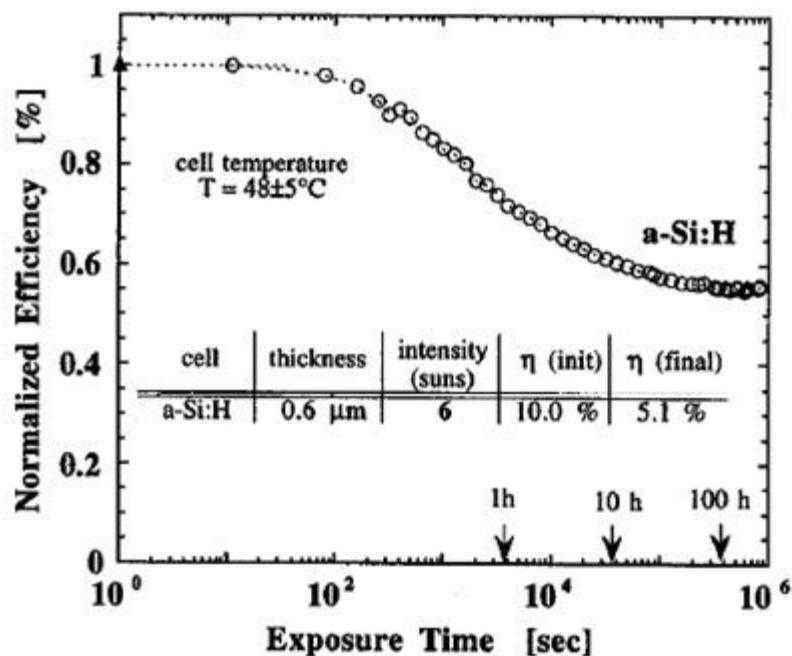


Fig. 15: Normalized cell efficiency of an a-Si:H p-i-n cell

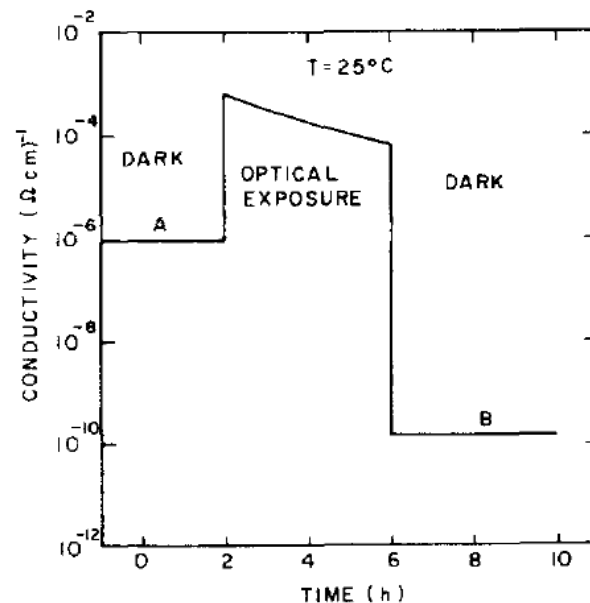


FIG. 1. Conductivity as a function of time before, during, and after exposure to ~ 200 mW/cm² of light in the wavelength range 6000–9000 Å.

- Light absorption creates metastable defects in a-Si:H.
→ Inherent to amorphous nature, end of a-Si:H as a PV technology...

Variations around a-Si:H

- Band gap increase possible through alloying with O or C (> 2 eV):

Morimoto, T. et al., J. Appl. Phys., 1982.

K. Haga, H. Watanabe, Jpn. J. Appl. Phys., 1990.

- Band gap decrease possible through alloying with Ge:

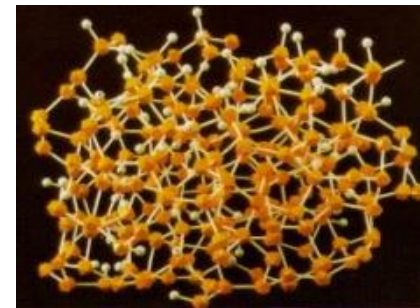
M. Stutzmann et al., J. Appl. Phys., 1989.

Issue: alloying yields more defective material...

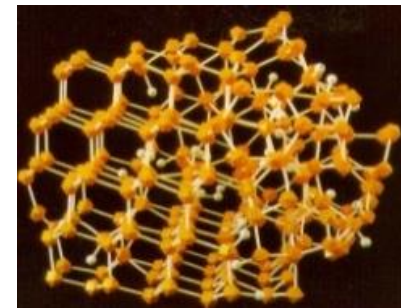
- Microcrystalline material can be grown from H-rich plasma (BG = 1.1 eV)

J.Meier, et al., *Appl. Phys. Lett.*, 1994.

										helium 2 He 4.0026
		boron 5 B 10.811	carbon 6 C 12.011	nitrogen 7 N 14.007	oxygen 8 O 15.999	fluorine 9 F 18.998	neon 10 Ne 20.180			
		aluminium 13 Al 26.982	silicon 14 Si 28.086	phosphorus 15 P 30.974	sulfur 16 S 32.065	chlorine 17 Cl 35.453	argon 18 Ar 39.948			
copper 29 Cu 63.546	zinc 30 Zn 65.39	gallium 31 Ga 69.723	germanium 32 Ge 72.61	arsenic 33 As 74.922	selenium 34 Se 78.96	bromine 35 Br 79.904	krypton 36 Kr 83.80			
silver 47 Ag 107.87	cadmium 48 Cd 112.41	indium 49 In 114.82	tin 50 Sn 118.71	antimony 51 Sb 121.76	tellurium 52 Te 127.60	iodine 53 I 126.90	xenon 54 Xe 131.29			
gold 79 Au 196.97	mercury 80 Hg 200.59	thallium 81 Tl 204.38	lead 82 Pb 207.2	bismuth 83 Bi 208.98	polonium 84 Po [209]	astatine 85 At [210]	radon 86 Rn [222]			



Amorphous silicon



Microcrystalline silicon

Variations around a-Si:H

C incorporation in a-SiC:H depends on C precursor...

[W. Beyer and H. Mell, in Disordered Semiconductors, edited by Kastner, Thomas, and Ovshinsky (Springer US, 1987)]

TEM:
size and shape of the grains

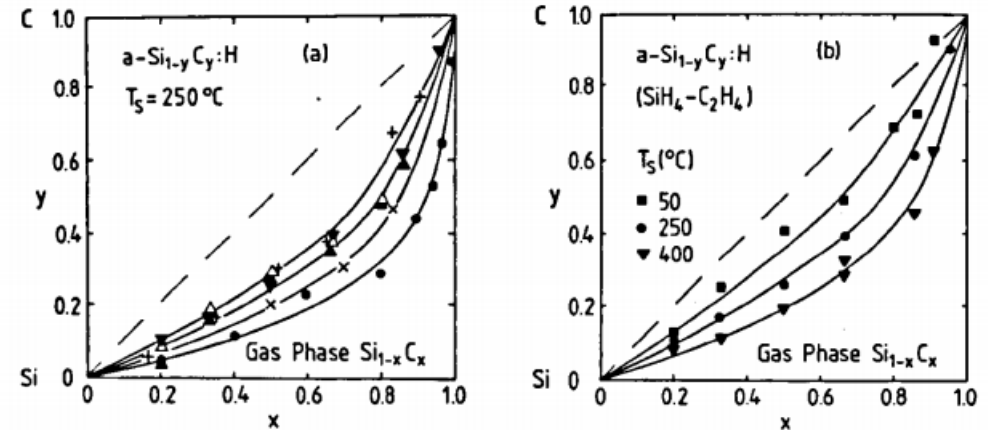
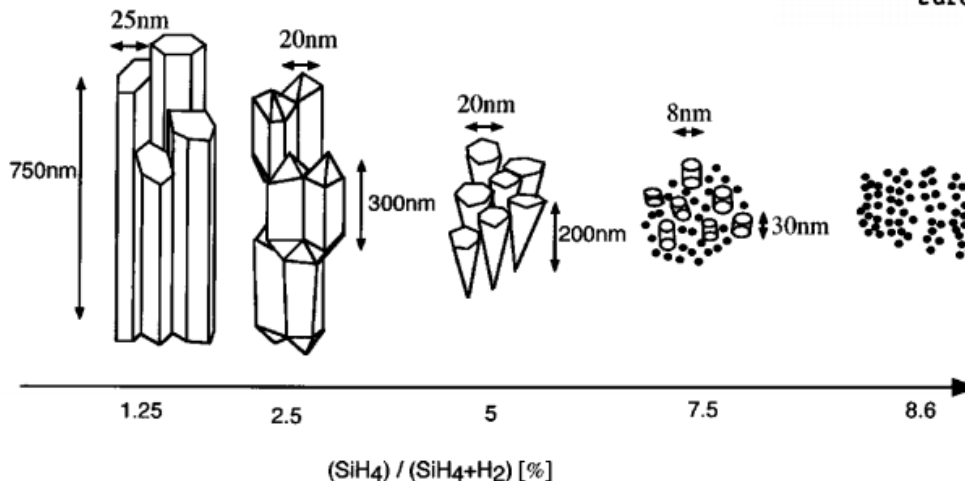
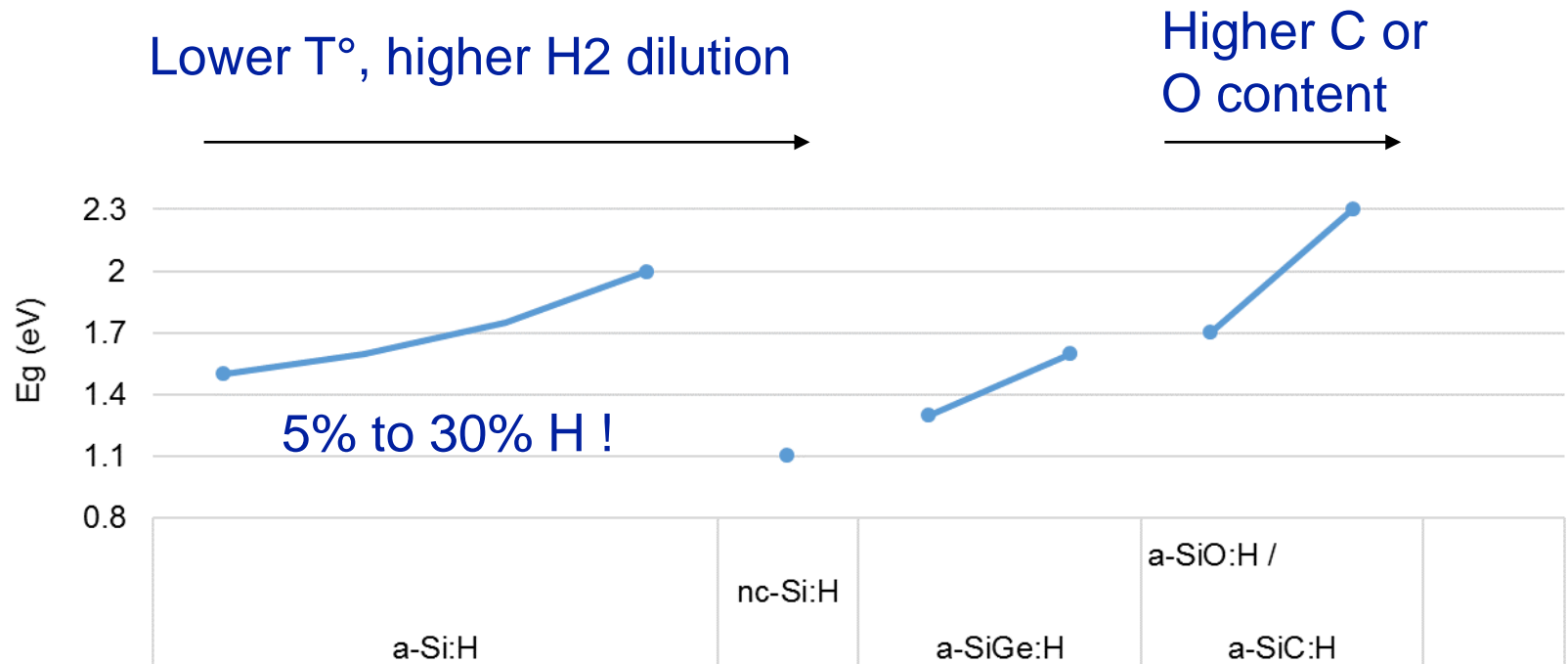


Fig. 1 Composition parameter y versus gas phase mixture parameter x (a) for the mixtures $\text{SiH}_4\text{-CH}_4$ (●), $\text{SiH}_4\text{-C}_2\text{H}_6$ (▲), $\text{SiD}_4\text{-C}_2\text{D}_6$ (Δ), $\text{SiH}_4\text{-C}_2\text{H}_4$ (▼), $\text{Si}_2\text{H}_6\text{-CH}_4$ (×) and $\text{Si}_2\text{H}_6\text{-C}_2\text{H}_4$ (+), (b) for the mixture $\text{SiH}_4\text{-C}_2\text{H}_4$ deposited at different substrate temperatures.

Low $\text{SiH}_4 / \text{H}_2$ ratio
→ crystalline growth

[Vallat Sauvain *et al*, JAP **87**, p3141 (2000)]

Variations around a-Si:H

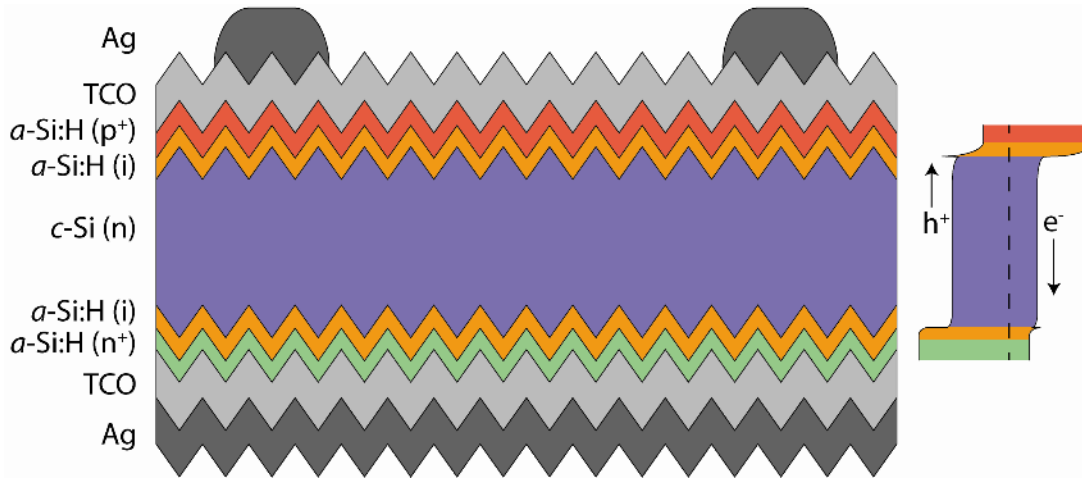


All layers are conducting enough (even undoped)
for charge collection unlike SiN_x, Al₂O₃, ...
→ Passivating contact possibility !

“usable range” for
heterojunctions,
wider E_G possible

From homo- to heterojunction solar cell

Heterojunction solar cell



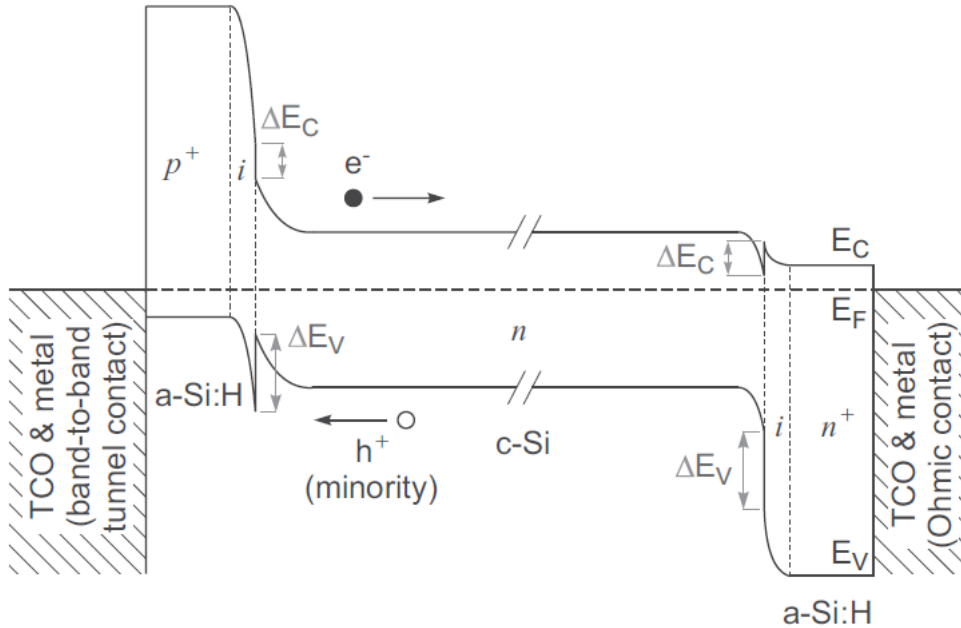
- Si surface passivation from (i)a-Si:H
- Selectivity induced by doped a-Si:H
- Lateral transport provided by TCO (metal on rear)

But...

All layers are interlinked and influence each other !

- Doped layers influence passivation
- TCO influences passivation
- TCO influences selectivity
- ...

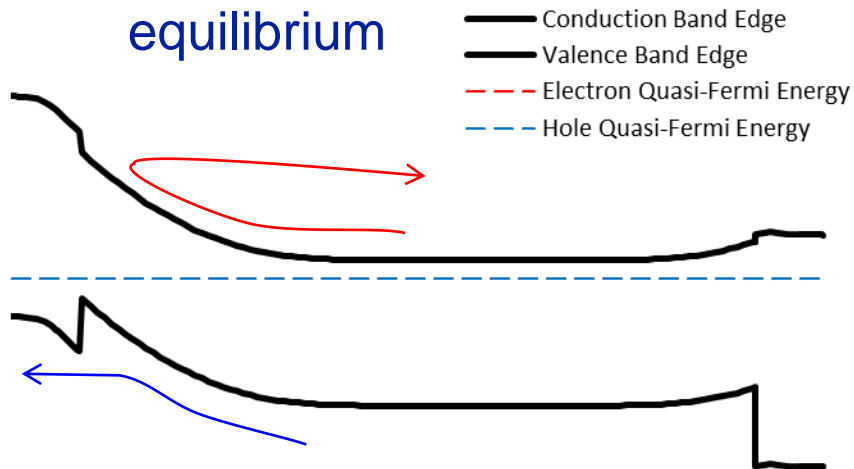
Heterojunction c-Si technology



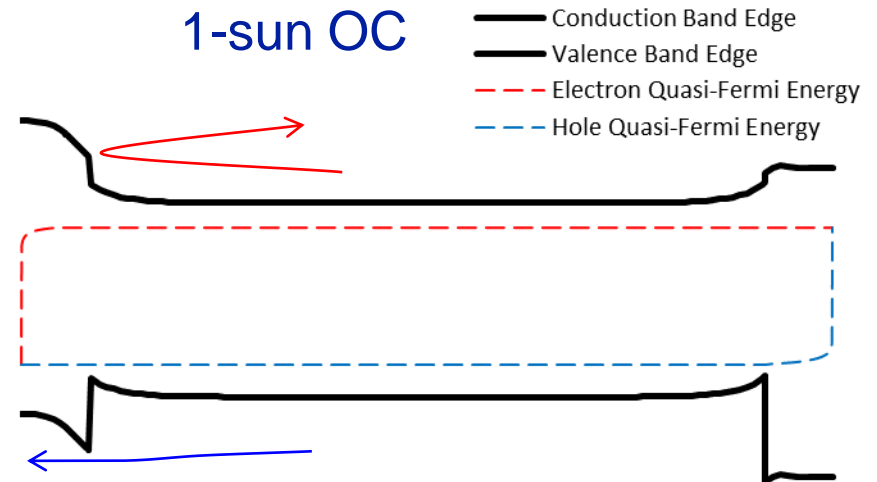
Band bending, band offsets, surface inversion often represented in equilibrium...

Heterojunction c-Si technology

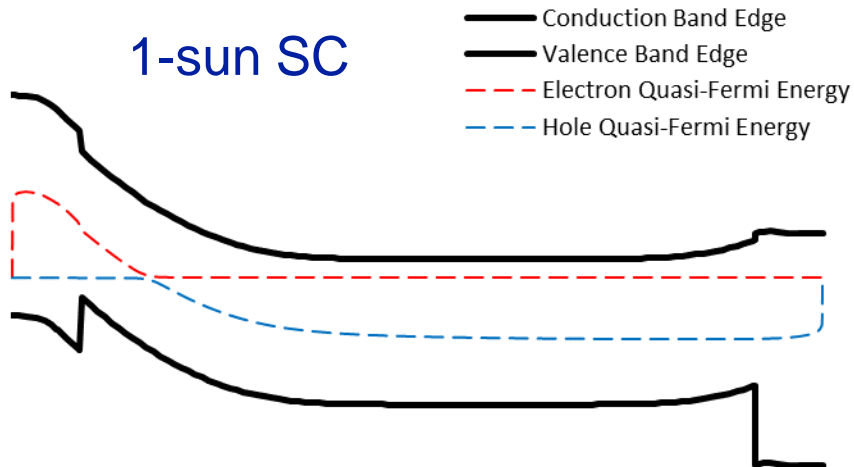
equilibrium



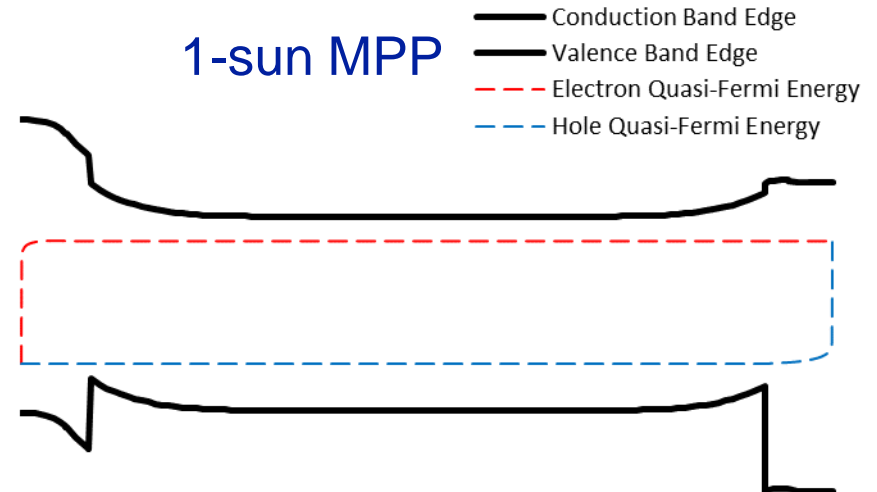
1-sun OC



1-sun SC



1-sun MPP



Process flow

Chemical
baths
c-Si surface
preparation

PECVD I
Intrinsic
film
deposition
a-Si:H(i)



PECVD a-Si:H

Process:

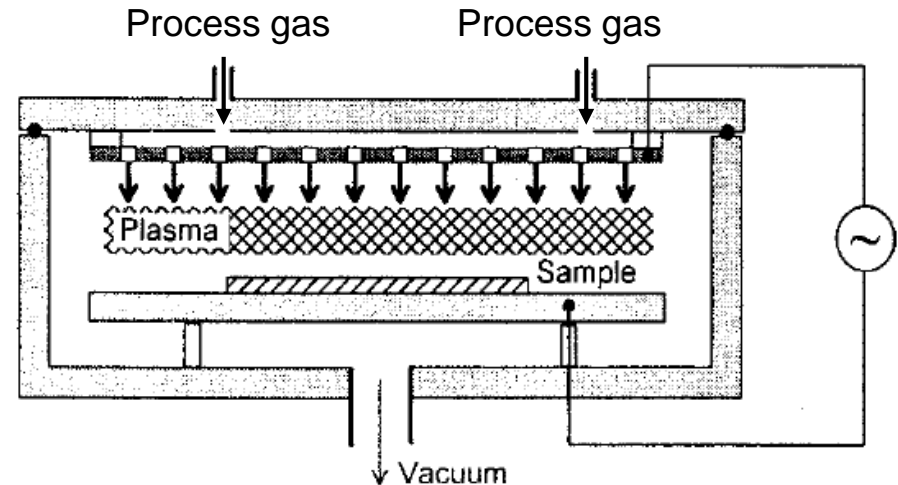
plasma enhanced chemical vapour deposition

Features:

- Process-gas: silane (SiH_4) + hydrogen (H_2)
- Films can be doped by adding dopant gasses
- Deposition-rate: $\sim 1\text{-}10 \text{ \AA/s}$
- Deposition-temperature: ~ 200 degrees C
- Cross-contamination may be an issue, hence use of separate chambers for intrinsic, p-type, and n-type deposition
- employed gasses can be explosive and / or toxic – caution needed !
→ non-ideal safety-wise

Intrinsic films

Amorphous silicon deposition



*Taken from Aberle & Hezel, Prog. in Photovolt.:
Res. Appl. 5 (1997) 29-50*

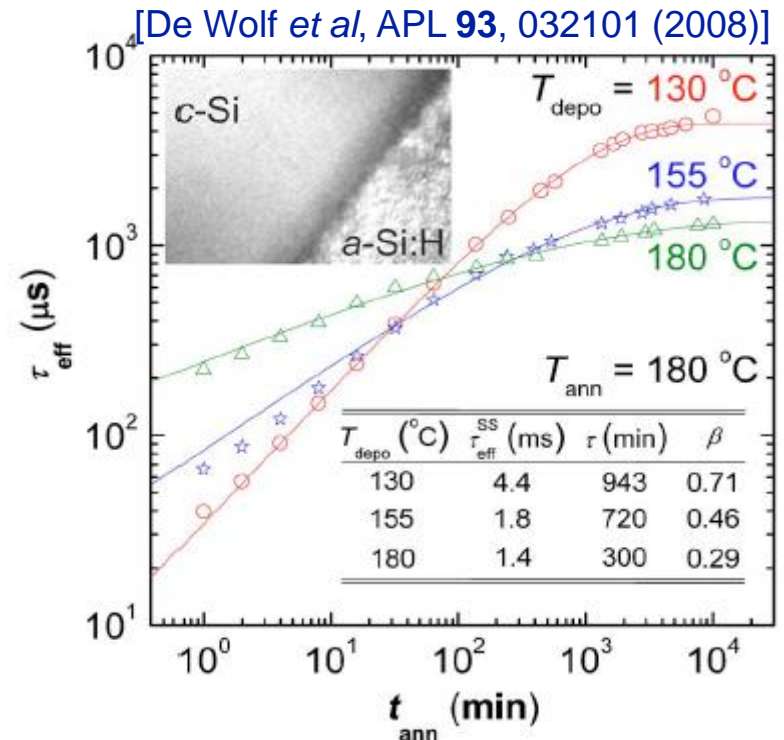
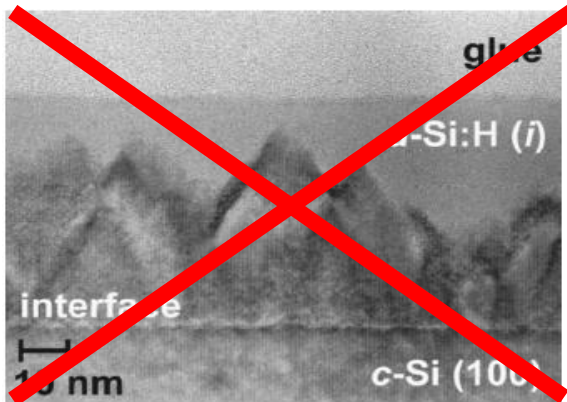
Key points passivation I

Many in-depth papers from De Wolf

- Epitaxy is detrimental to passivation—only amorphous films passivate c-Si?
- ~200 °C annealing of a-Si:H can yield strong improvements

Intrinsic films

[De Wolf *et al*, APL **90**, 042111 (2007)]

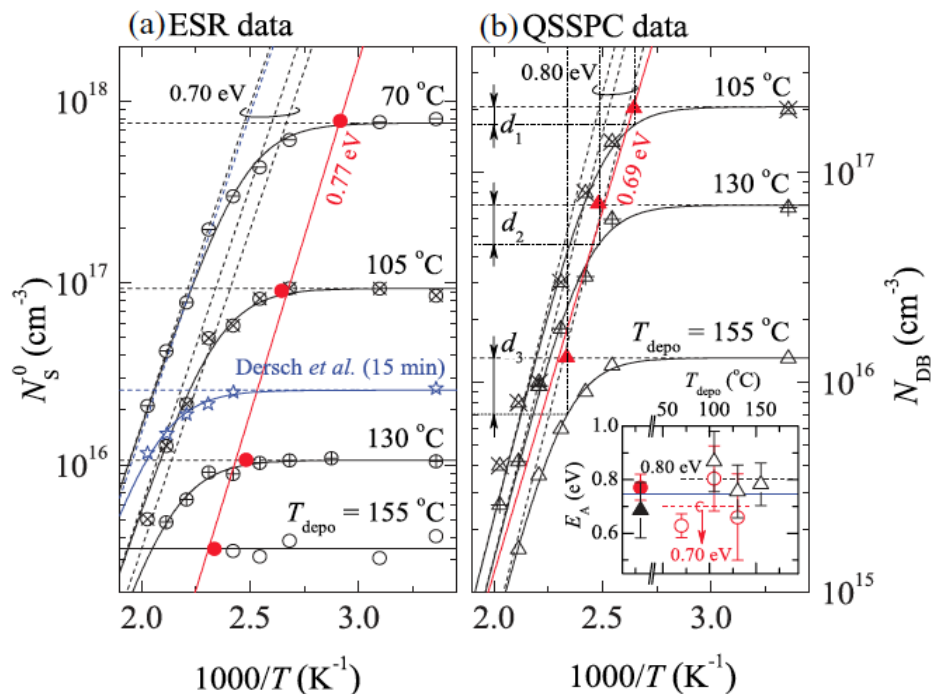


Key points passivation I

Intrinsic films

Many in-depth papers from De Wolf

- Epitaxy is detrimental to passivation
- ~200 °C annealing of a-Si:H can yield strong improvements
- Defects at c-Si/a-Si:H interface are similar to bulk a-Si:H defects



[De Wolf et al, PRB **85**, 113302 (2012)]

For a-Si:H/c-Si interface

Energy barrier of ~0.75 eV,
independent of deposition conditions as well

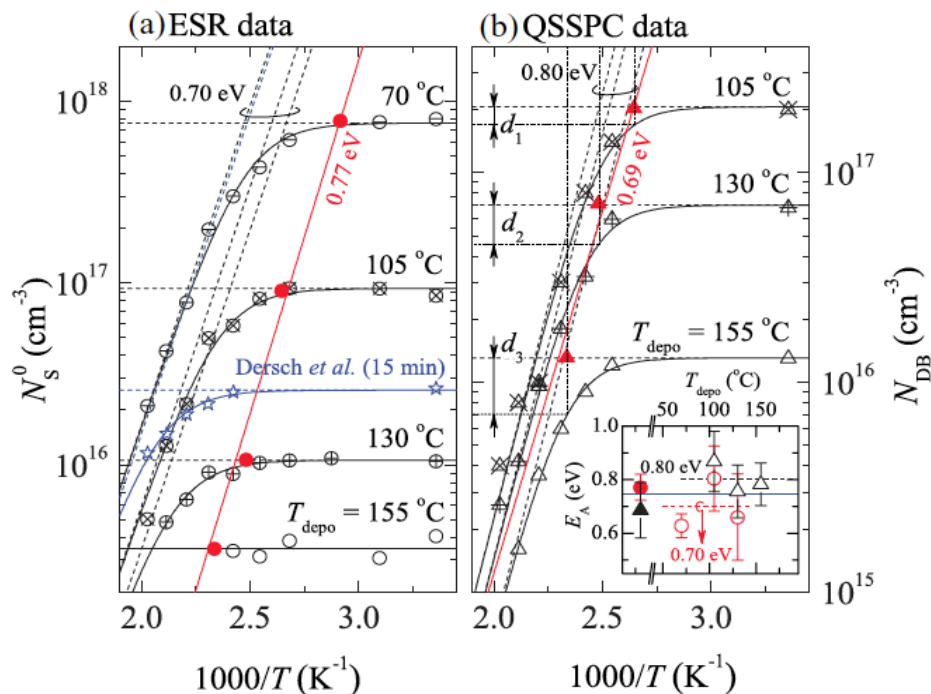
- 1) Physical evidence that interface states are dangling bonds as well
- 2) Evidence that a-Si:H/c-Si interface has no unique properties compared to a-Si:H bulk

Key points passivation I

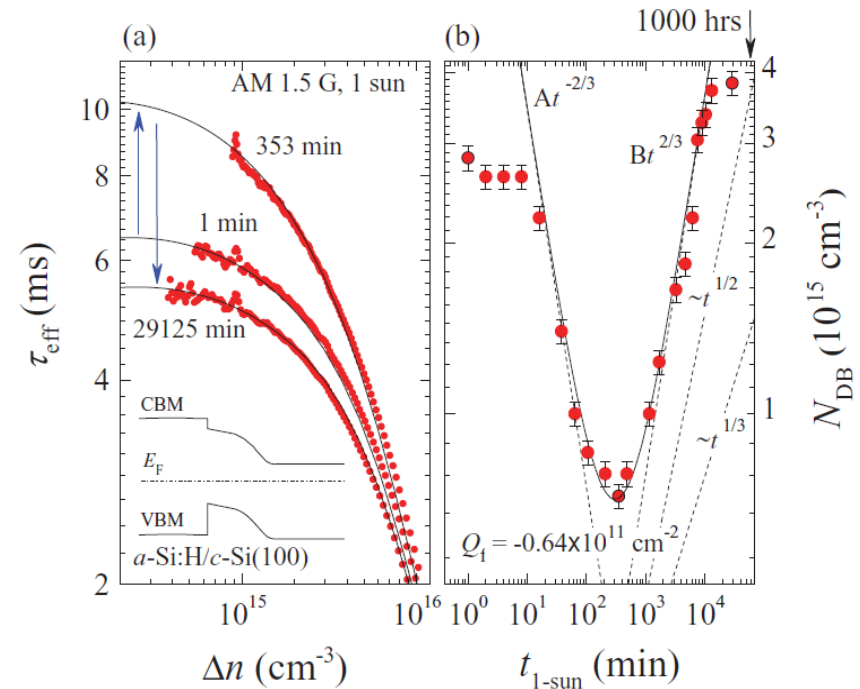
Many in-depth papers from De Wolf

- Epitaxy is detrimental to passivation
- ~200 °C annealing of a-Si:H can yield strong improvements
- Defects at c-Si/a-Si:H interface are similar to bulk a-Si:H defects
- Light-induced degradation also impedes passivation

Lifetime is a very sensitive probe to small changes in defect density !



[De Wolf et al, PRB **85**, 113302 (2012)]



[De Wolf et al, PRB **83**, 233301 (2011)]

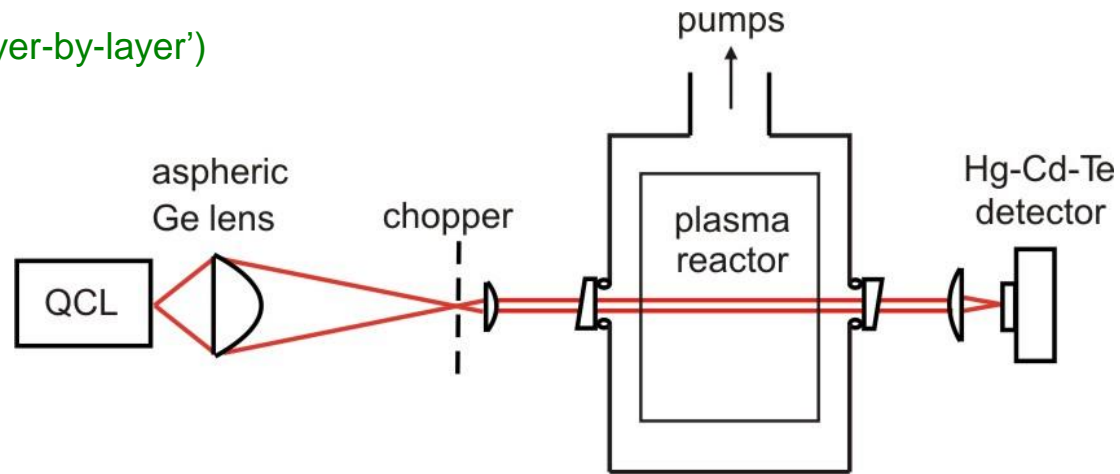
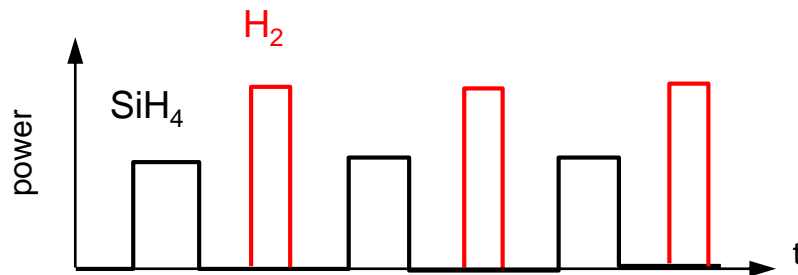
Key points passivation I

For good devices:

- Go towards the amorphous-to-crystalline transition as much as possible, but NO EPITAXY !

- Use highly depleted silane plasmas
- H_2 plasma during a-Si:H growth ('layer-by-layer')

[Bartlome *et al*, APL
94, 201501 (2009)]



[Descoeudres *et al*., APL
97, 183505 (2010)]

Intrinsic films

Key points passivation I

For good devices:

- Go towards the amorphous-to-crystalline transition as much as possible, but NO EPITAXY !

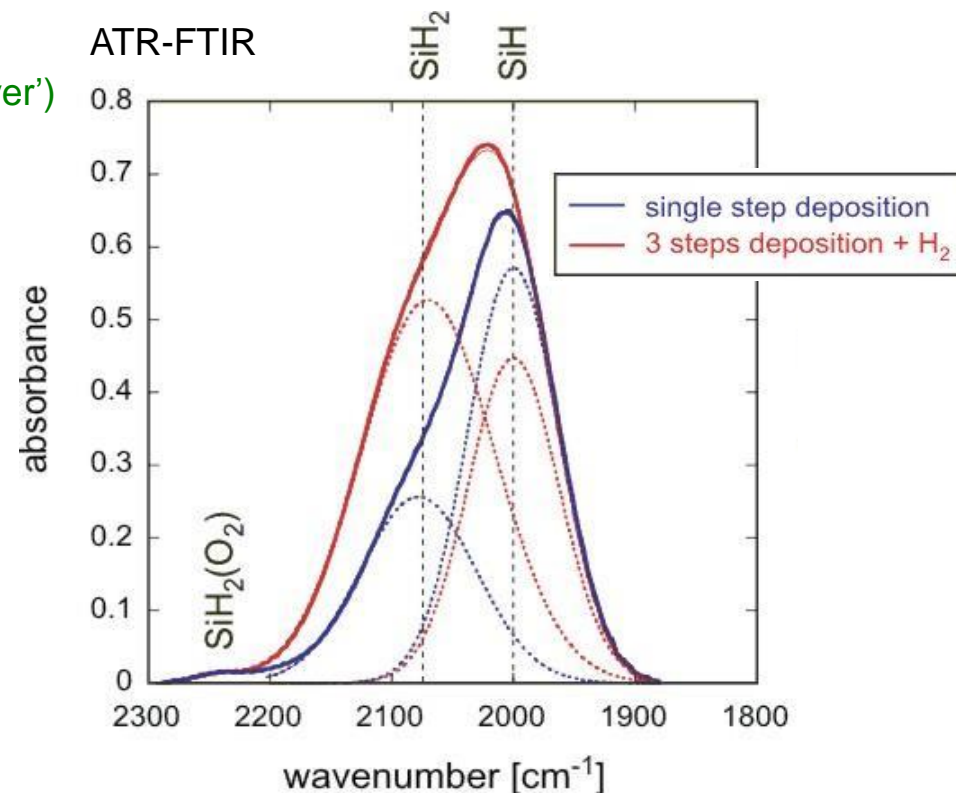
- Use highly depleted silane plasmas
- H_2 plasma during a-Si:H growth ('layer-by-layer')

- Layer properties

- Increase in hydrogen content
- Increase in band gap
- More disordered
- Etching effect if H_2 plasma is too long

[Descoeurdes *et al.*, APL
99, 123506 (2011)]

Intrinsic films



Key points passivation I

For good devices:

- Go towards the amorphous-to-crystalline transition

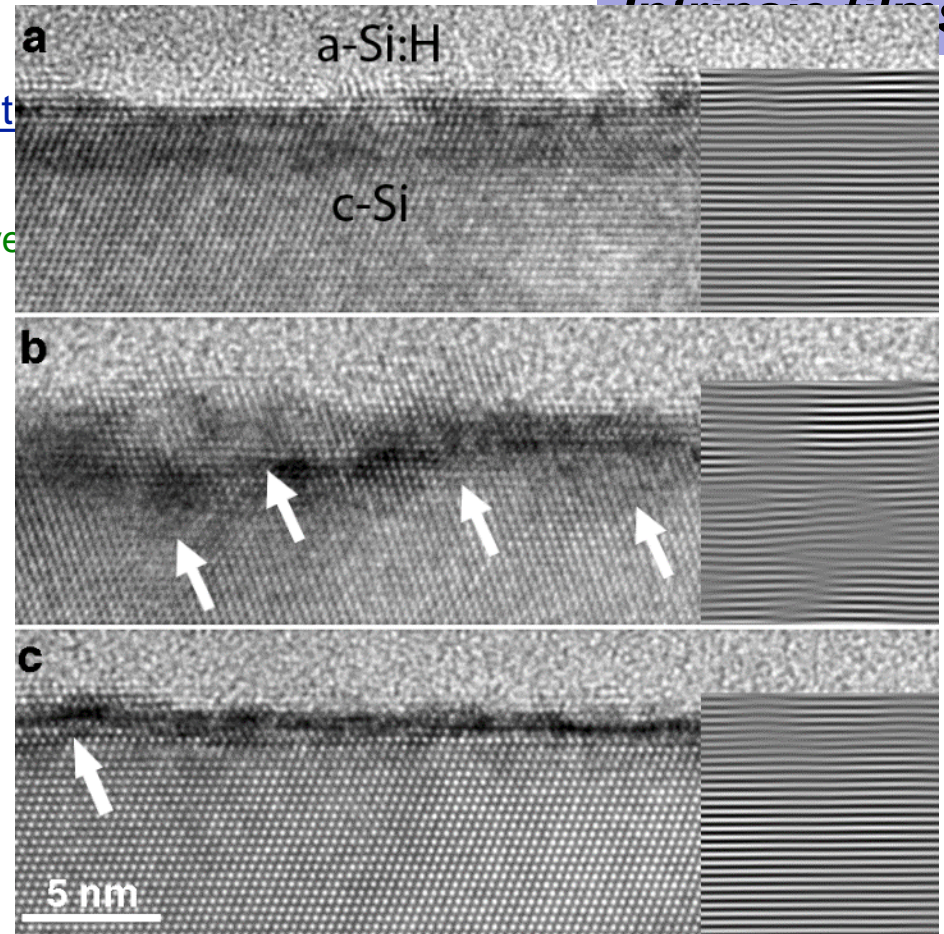
- Use highly depleted silane plasmas
- H_2 plasma during a-Si:H growth ('layer-by-layer')

- Layer properties

- Increase in hydrogen content
- Increase in band gap
- More disordered
- Etching effect if H_2 plasma is too long
- Minimum buffer layer thickness to be present!

- Globally beneficial for devices

➔ 5-20 mV gain in V_{oc}

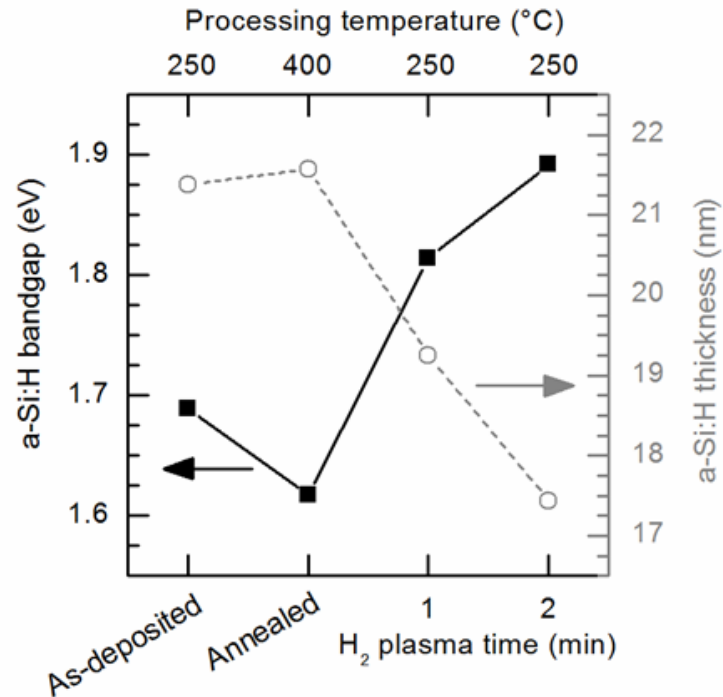
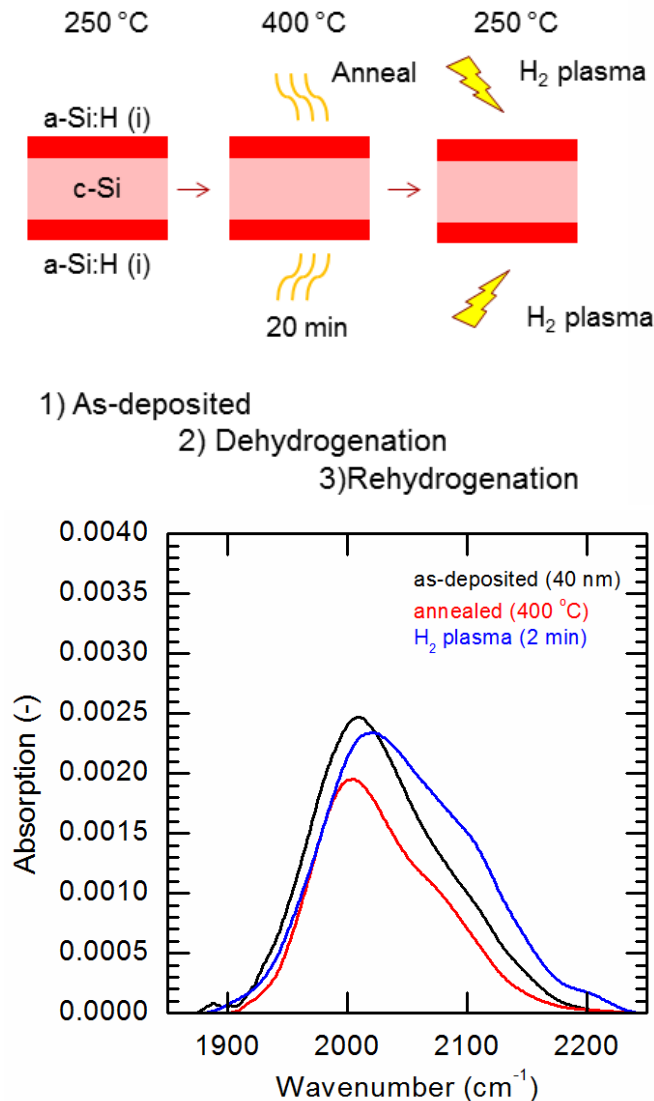


[Geissbuehler *et al.*, APL **102**, 231604 (2013)]

De-hydrogenation and rehydrogenation

J. Shi *et al.*, *Appl. Phys. Lett.* **109**, 031601 (2016)

Intrinsic films

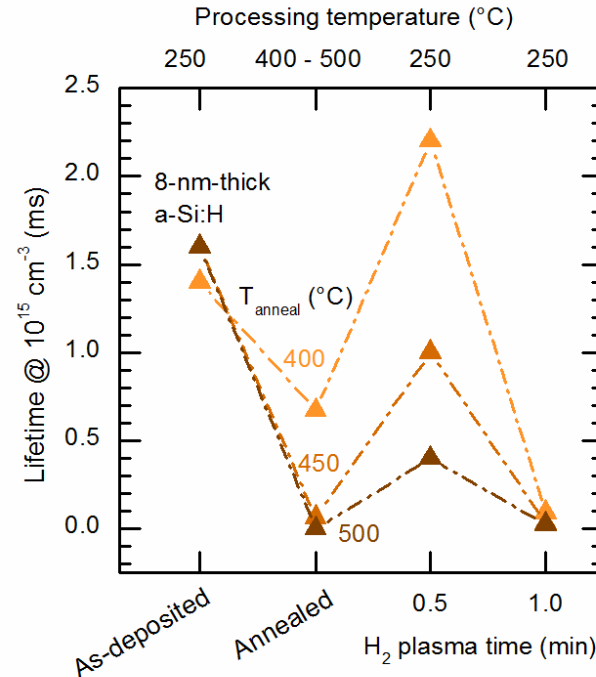
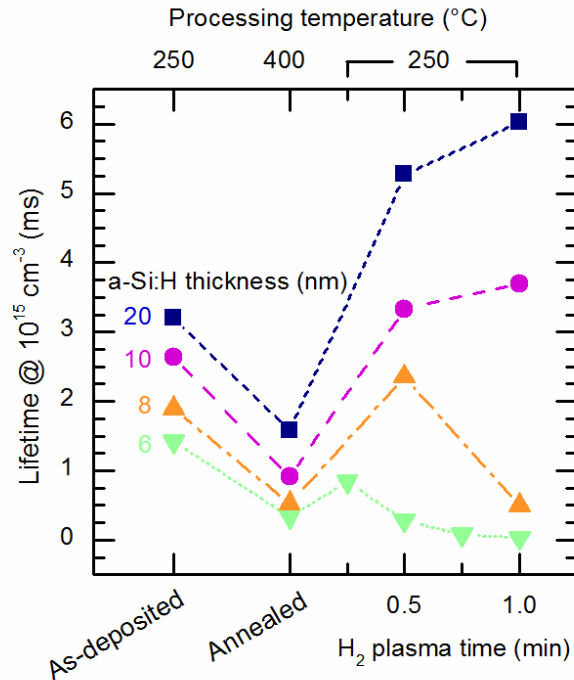


- De-hydrogenation and re-hydrogenation visible through ellipsometry and FTIR
- Very slow etching rate ~2 nm/min

De-hydrogenation and rehydrogenation

J. Shi *et al.*, *Appl. Phys. Lett.* **109**, 031601 (2016)

Intrinsic films



- Re-hydrogenation with H₂ plasma allows to recover initial lifetime after high-temperature annealing
 - Only for thick-enough layers
 - Only up to certain temperature (e.g. here 500 °C)
 - Too long plasma is detrimental to passivation **before complete etching**

Process flow

Chemical
baths
c-Si surface
preparation

PECVD I
Intrinsic
film
deposition
a-Si:H(i)

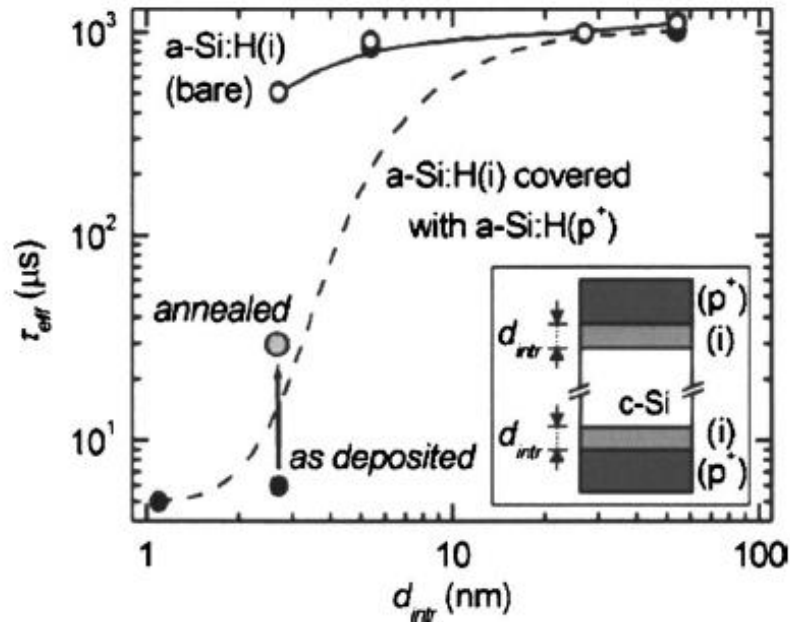
PECVD II
Doped film
deposition
a-Si:H(n/p)



Doped layers effect on passivation

- Doped-layer deposition on thin (i)a-Si:H can yield poor passivation

Doped films



General note:

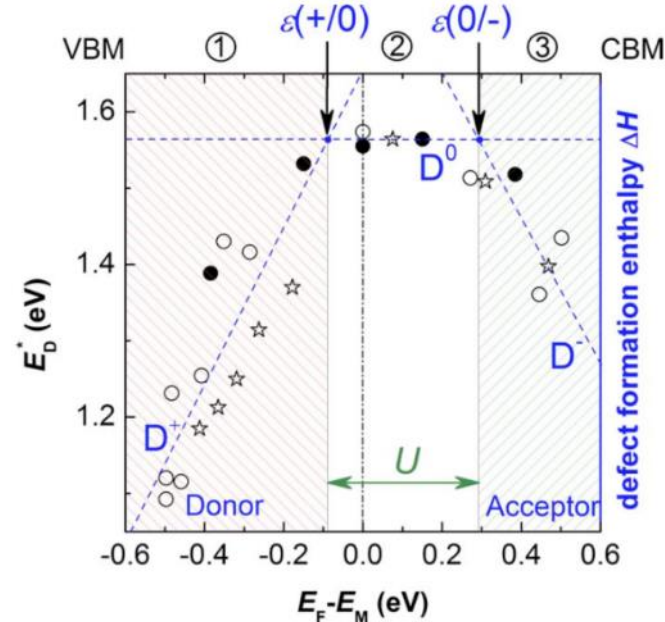
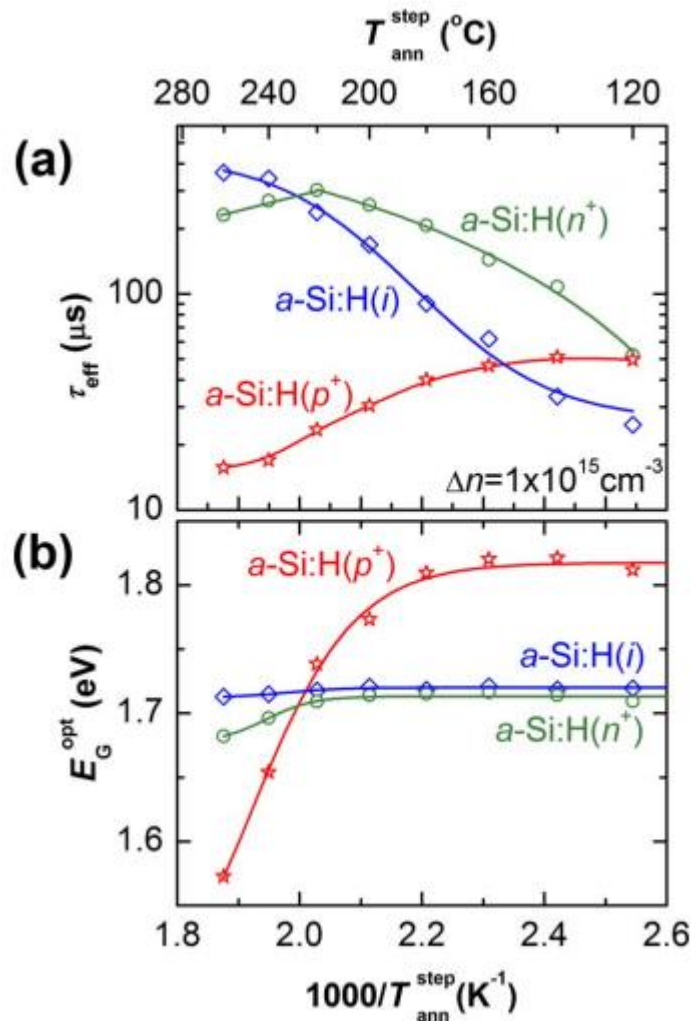
Doped layers are “easy” to develop, most effort is required for (i)a-Si:H.

[De Wolf *et al*, APL **88**, 022104 (2006)]

Doped layers effect on passivation

S. De Wolf and M. Kondo, *J. Appl. Phys.* **105**, 103707 (2009)

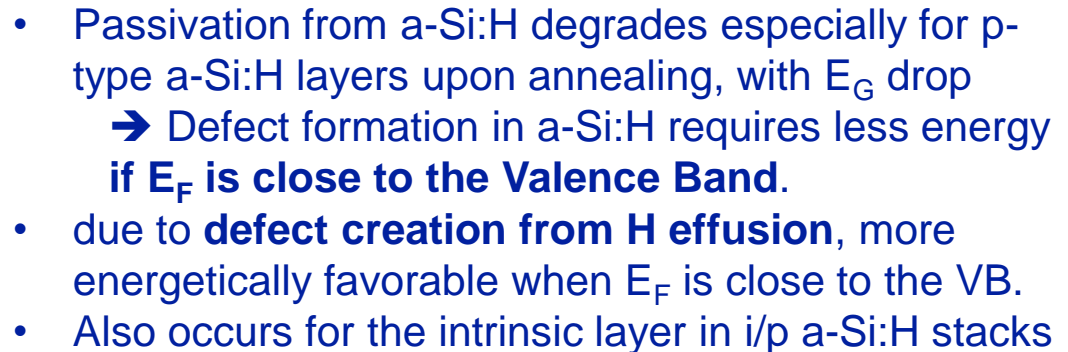
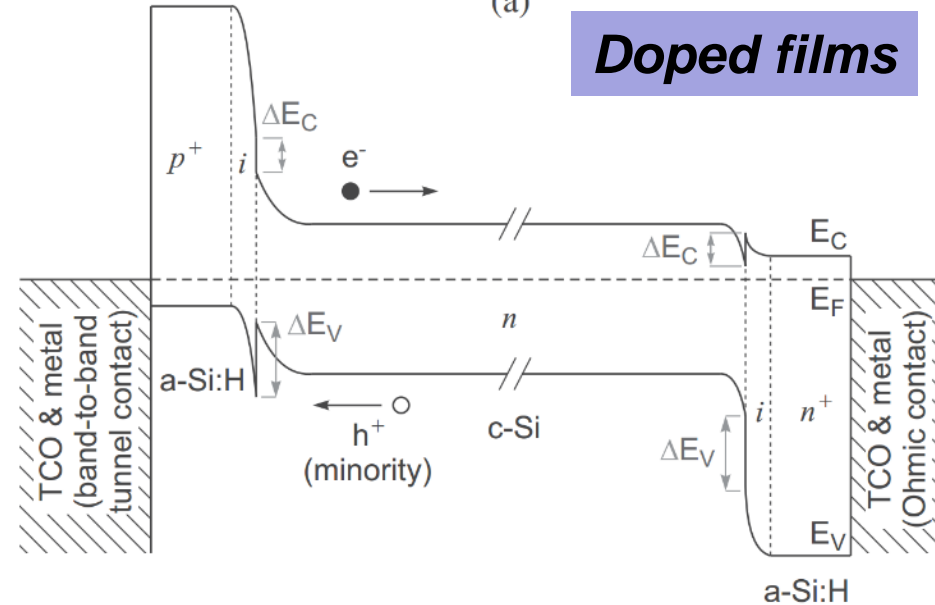
Doped films



- Passivation from a-Si:H degrades especially for p-type a-Si:H layers upon annealing, with E_G drop
 → Defect formation in a-Si:H requires less energy if E_F is close to the Valence Band.

Doped films

(a)



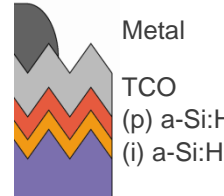
Doped layers effect on passivation

L. Barraud et al., Silicon PV, (2016)

Potential passivation drop after
p-layer deposition

Linked to the
(i) a-Si:H layer properties

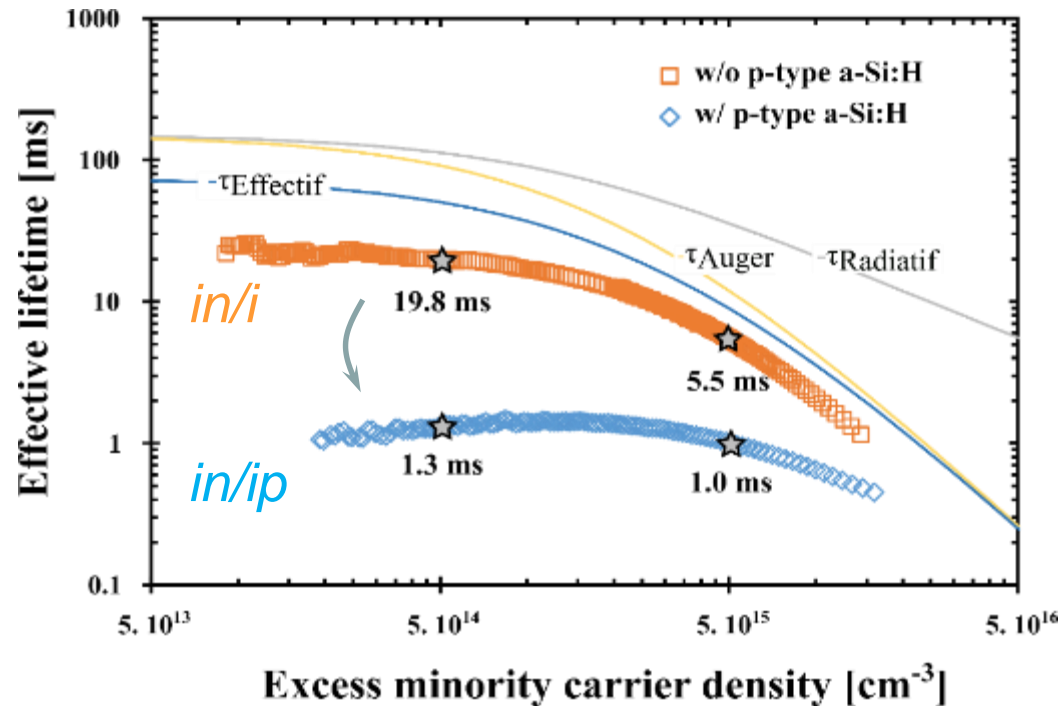
Hole-selective
passivating contact



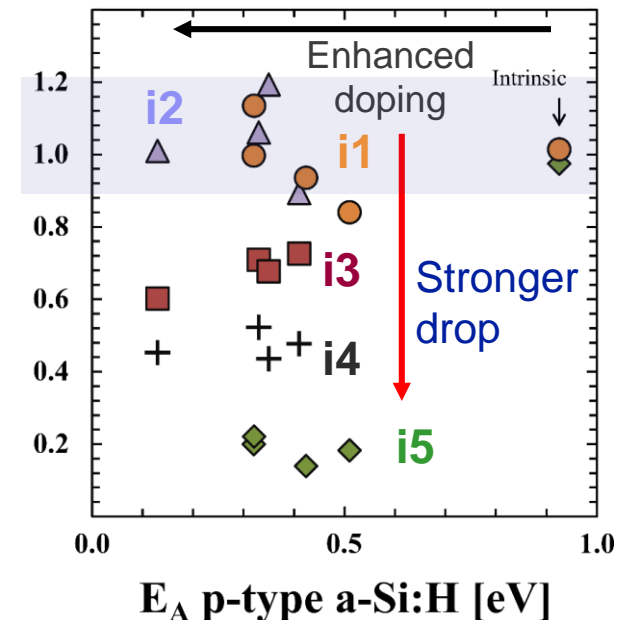
istrong

iweak

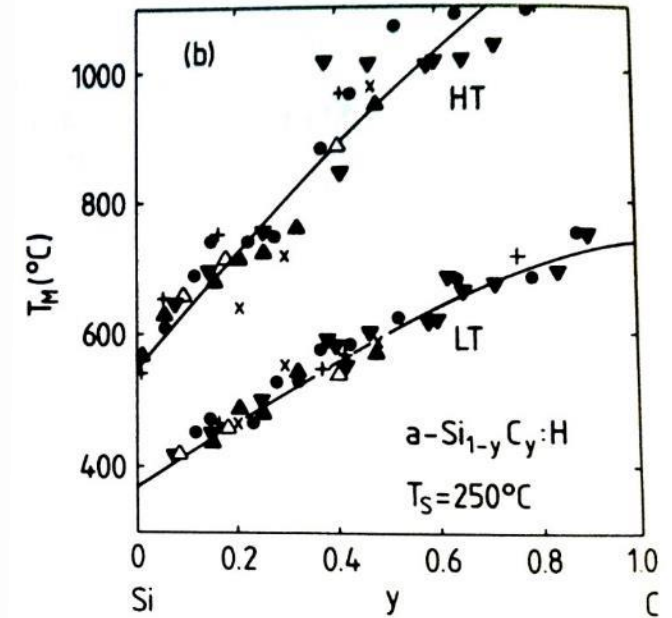
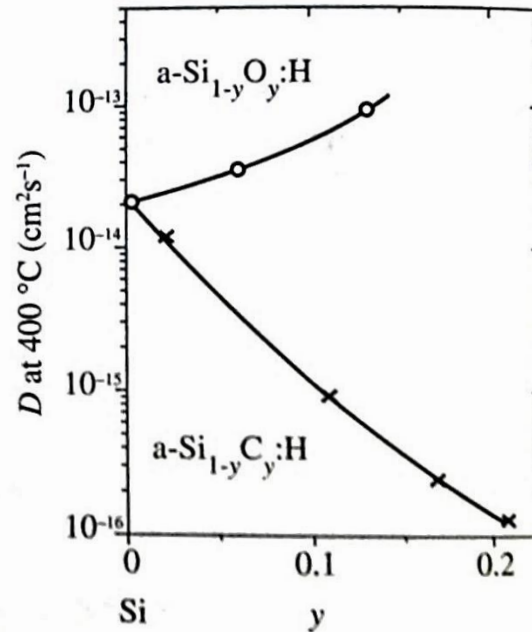
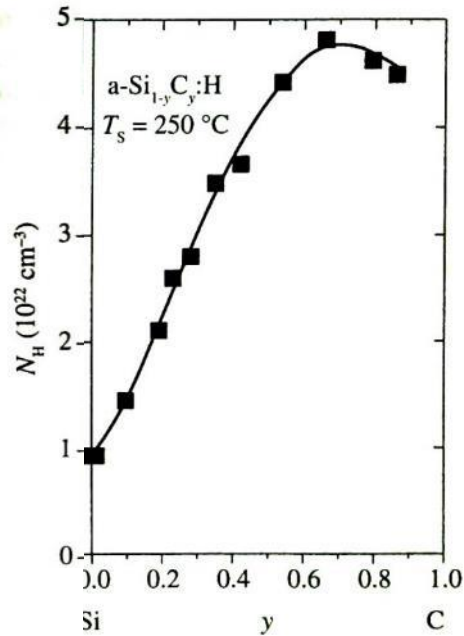
	Thickness* [nm]	Band gap [eV]	τ_{Eff} w/o p-type a-Si:H [ms]	τ_{Eff} w/ p-type a-Si:H [ms]
<i>istrong</i>	5.9	1.80	6.0	5.1
	7.1	1.83	2.1	2.2
	7.4	1.82	4.1	2.8
<i>iweak</i>	5.6	1.74	5.3	2.5
	7.2	1.75	5.3	1.3



Ratio τ_{Eff} after / before p-type



Better resilience towards H loss / defect formation

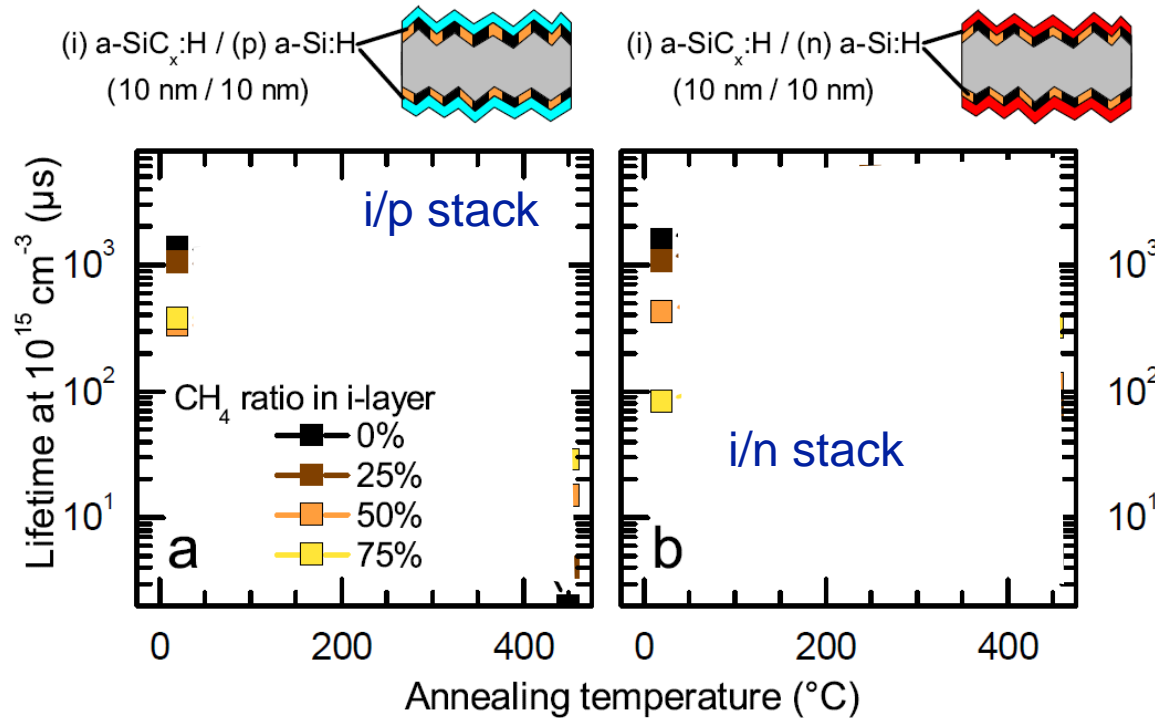


Binding energies:
Si-H : 3.0 eV – 3.2 eV
C-H : 3.4 eV – 3.9 eV

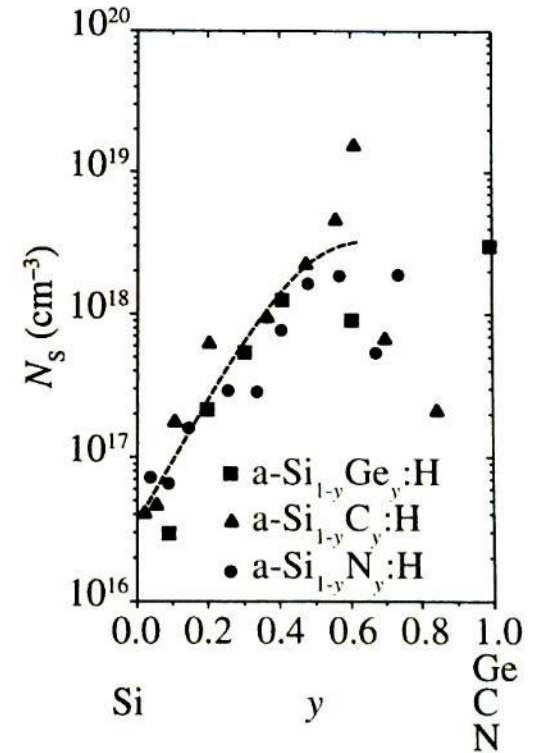
- H incorporation **increases** with C content,
- H diffusion coefficient **decreases** with C content,
- Temperatures of high- and low-temperature H-effusion maxima **increase** with C content.

W. Beyer in *Thin-Film Silicon Solar Cells*, A. Shah, (2010)

Better resilience towards H loss / defect formation



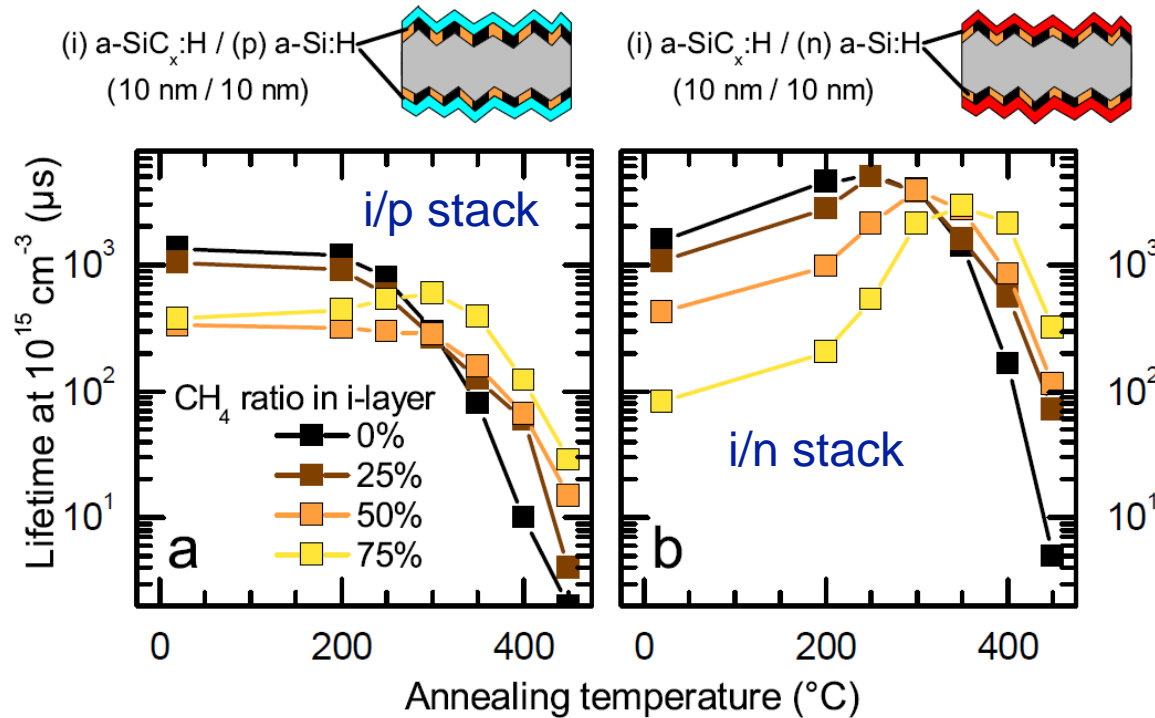
- passivation scales **down** with CH_4 ratio **initially**,



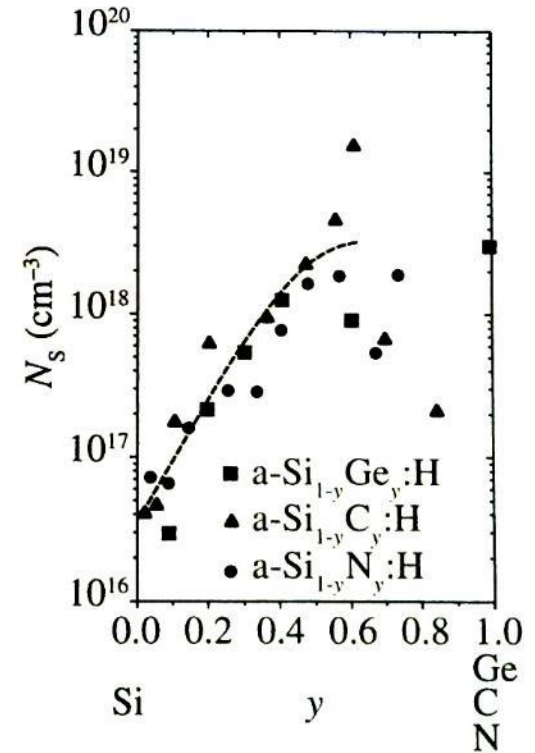
W. Beyer in *Thin-Film Silicon Solar Cells*, A. Shah, (2010)

M. Boccard and Z.C. Holman, *J. Appl. Phys*, **118**, 065704, (2015)

Better resilience towards H loss / defect formation



- passivation scales **down** with CH_4 ratio **initially**,
- yet it scales **up** with CH_4 ratio **passed 300 $^{\circ}\text{C}$** .
- i-p side limits lifetime in all cases.

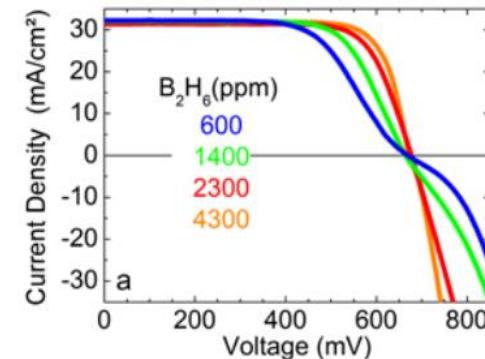
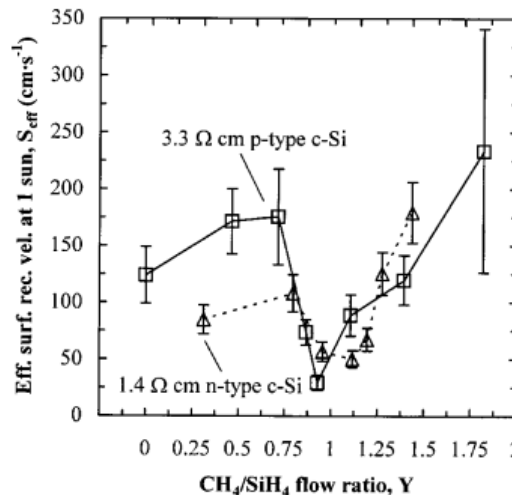
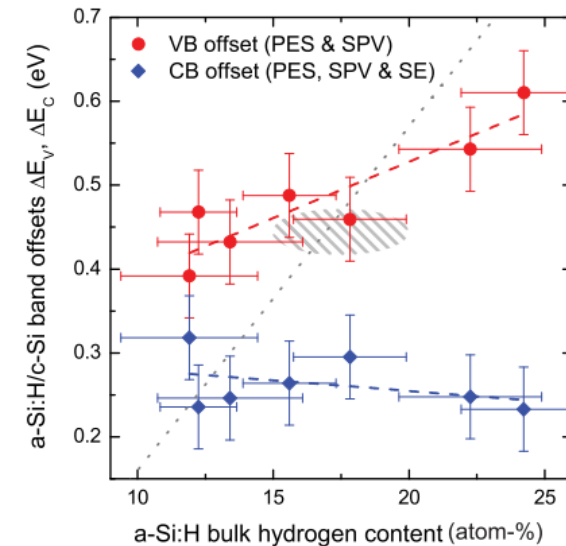


W. Beyer in *Thin-Film Silicon Solar Cells*, A. Shah, (2010)

M. Boccard and Z.C. Holman, *J. Appl. Phys*, **118**, 065704, (2015)

Further readings

- Fundamentals of passivation
 - De Wolf *et al.*, many more papers
 - Schultze, T. *et al.*, many papers
- Doped layers influence
 - Reusch *et al.*, Energy Procedia 38 (2013)
 - Bivour *et al.*, Solar Energy Materials & Solar Cells (2012)
 - Barraud *et al.*
- a-SiC:H / a-SiO:H
 - Martin *et al.*,
 - Mews *et al.*,
 - Mazzarella *et al.*,
 - Seif *et al.*,
- ... many more



Process flow

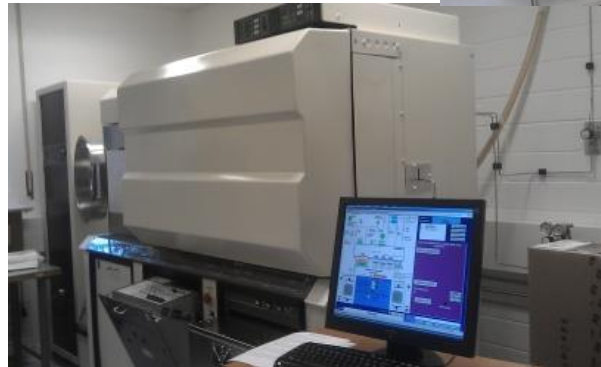
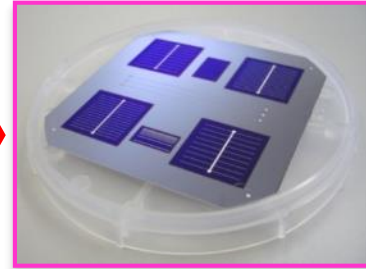
Chemical
baths
c-Si surface
preparation

PECVD I
Intrinsic
film
deposition
a-Si:H(i)

PECVD II
Doped film
deposition
a-Si:H(n/p)

PVD
TCO
sputtering

Metallization
Screen
printing
and curing
at 200° C



Sputtered TCO

Transparent conductive oxide deposition

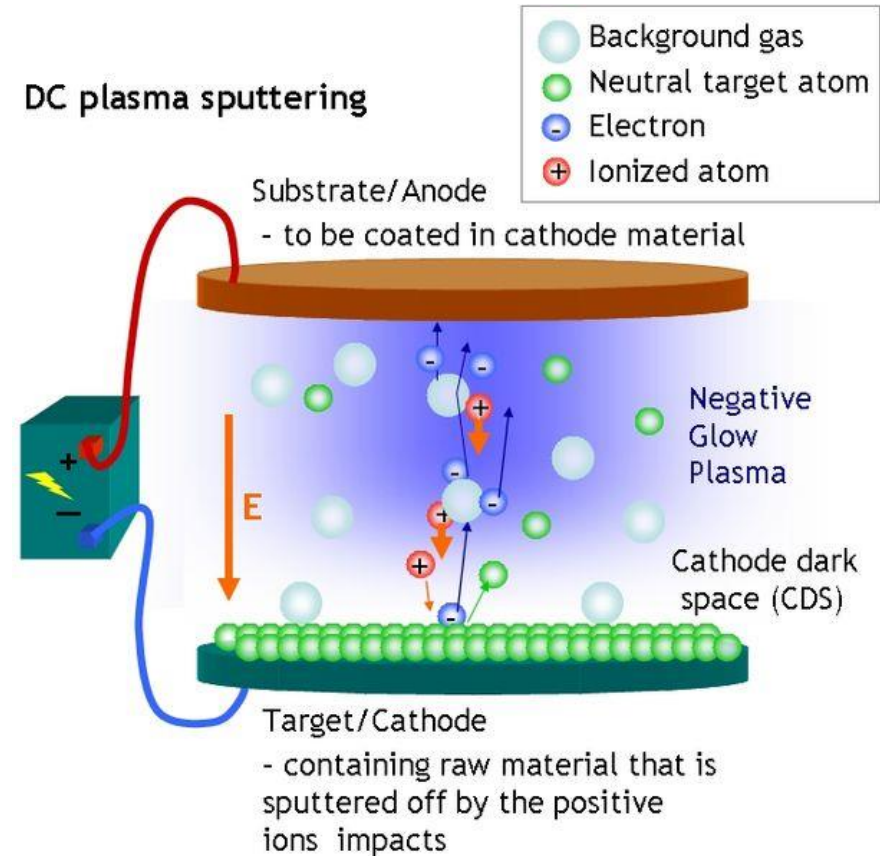
Process:

usually done by sputtering
(also known as physical vapour deposition)

Variants include DC and RF-sputtering
(shown example is DC sputtering)

Typical target-material: indium-tin-oxide (ITO)

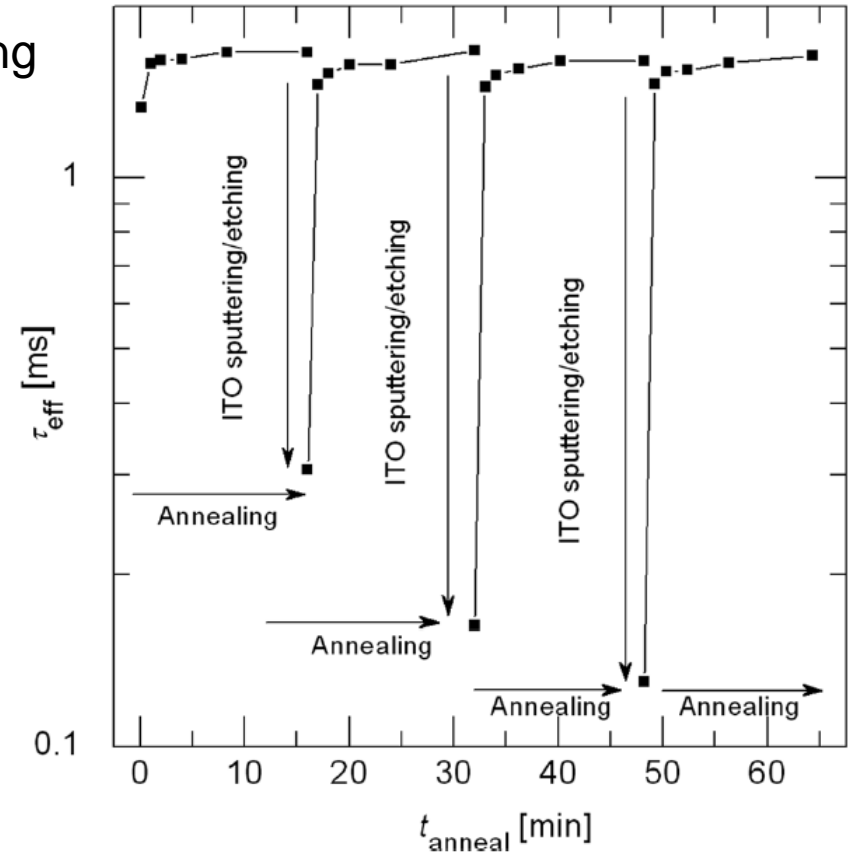
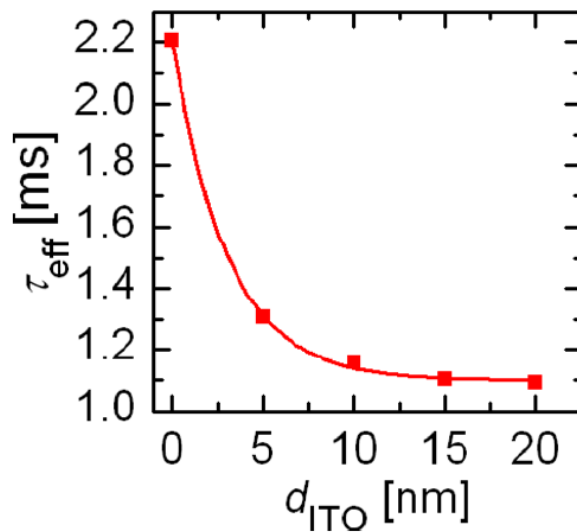
DC plasma sputtering



See e.g. M. Ohring, "Materials Science of Thin Films", 2nd Ed., Academic Press (2002)

Sputtered TCO

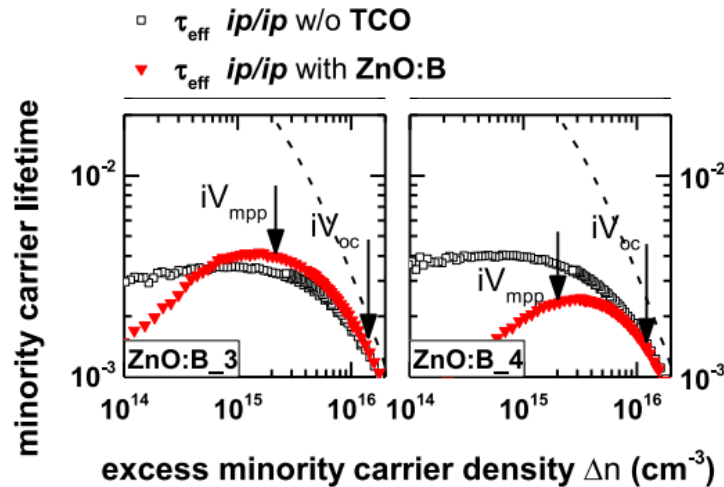
- Electronic passivation losses by sputtering
- Cause: plasma UV illumination + ...
- Curing → passivation restored



[Demaurex, *et al.* APL **101**, 171604 (2012)]

Sputtered TCO

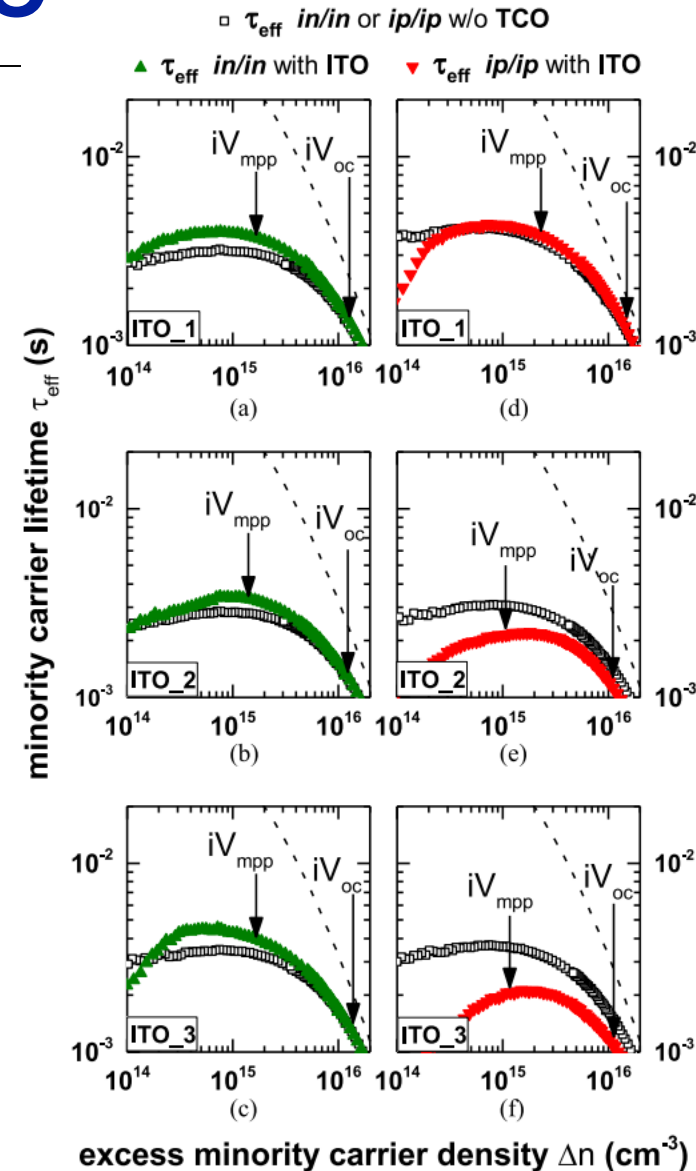
- Electronic passivation losses by sputtering
- Cause: plasma UV illumination + ...
- Curing → passivation restored
- ...Not always !



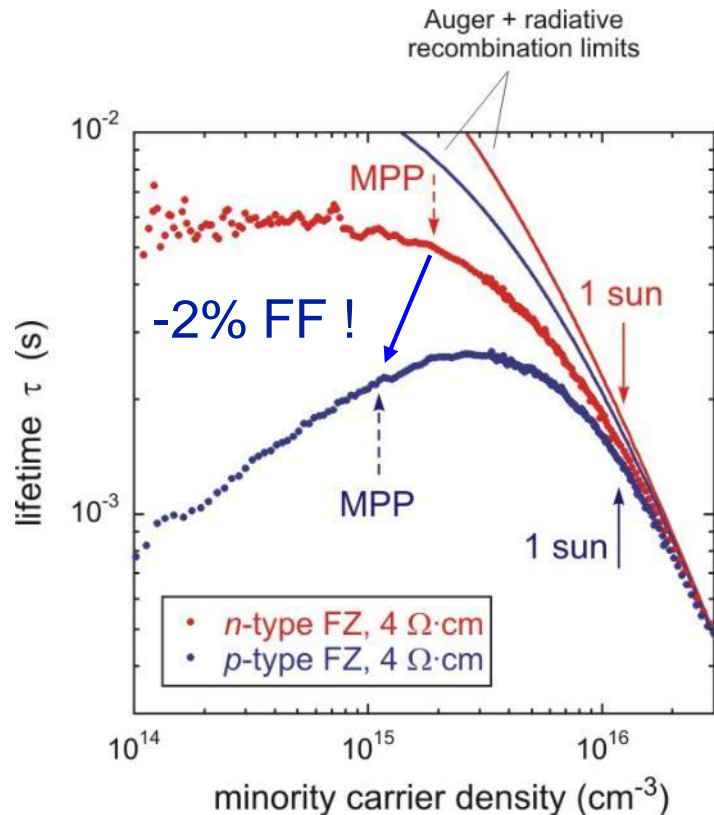
- Also occurring for “soft” deposition

[Tomasi, *et al.* IEEE JPV, (2016)]

Higher carrier concentration



Passivation : impact on FF



$$V^{implied} = \frac{kT}{q} \ln \left(\frac{(n_0 + Dn)(p_0 + Dp)}{n_0 p_0} \right)$$

- At open circuit $\rightarrow V_{oc}$
- At max powerpoint $\rightarrow V_{mpp} \rightarrow FF$

[A. Descoeudres *et al*, IEEE JPV **3**, 83 (2013)]

To obtain high FF : high V_{oc} not sufficient, high lifetime at MPP required as well

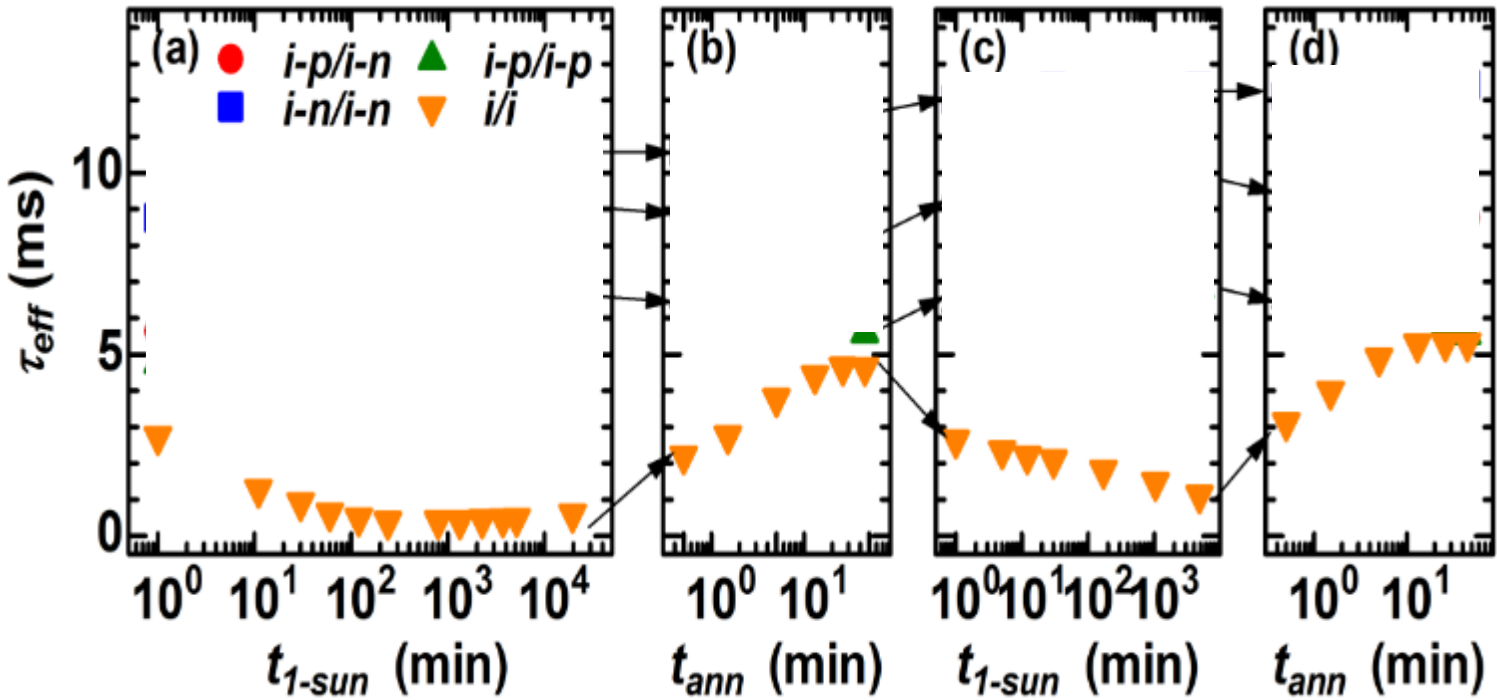
Light annealing effects on SHJ precursors: i-layer



Kobayashi et al. APL 2016

Light-induced performance increase of silicon heterojunction solar cells

Eiji Kobayashi, Stefaan De Wolf, Jacques Levrat, Gabriel Christmann, Antoine Descoeudres, Sylvain Nicolay, Matthieu Despeisse, Yoshimi Watabe, and Christophe Ballif



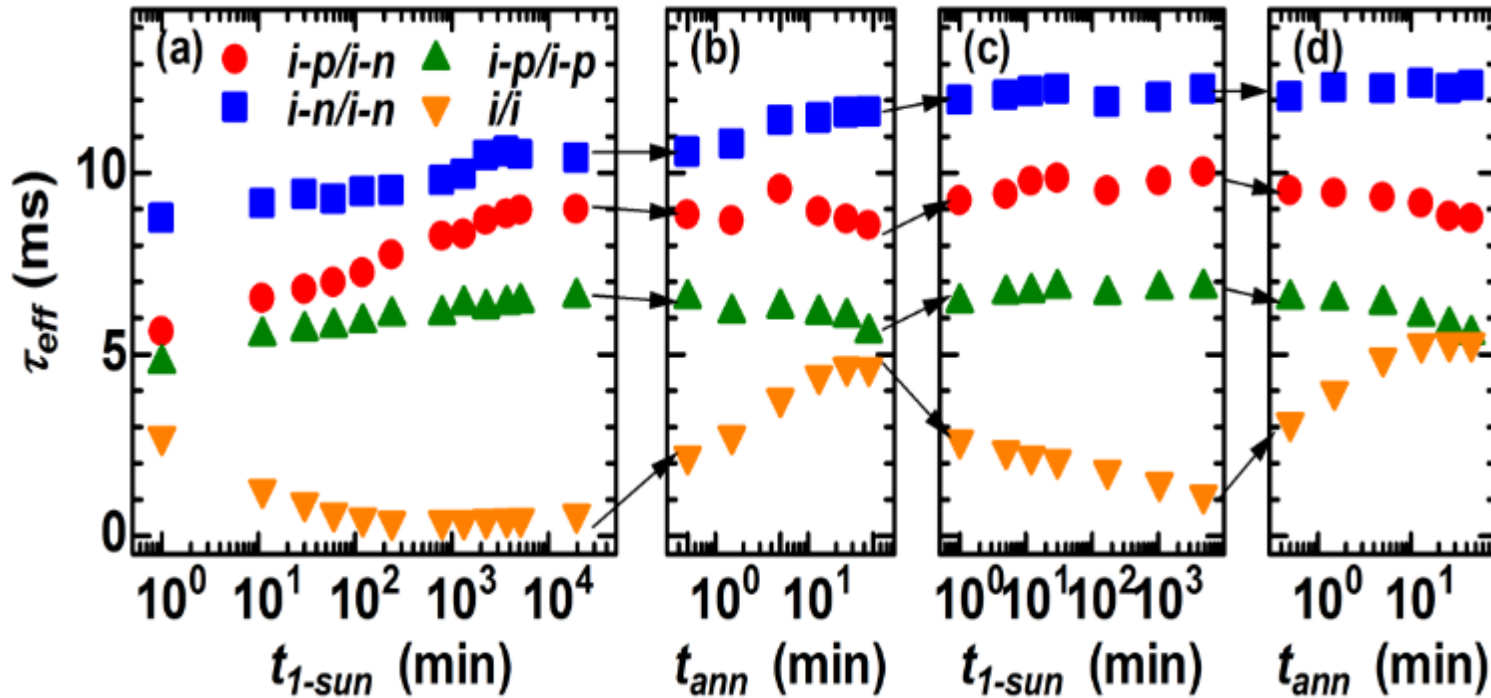
Lifetime **decrease** (= surface passivation decrease)

With intrinsic layers 

See also. **De wolf et al. 2006-2015**

Light annealing effects on SHJ: change with doped layers

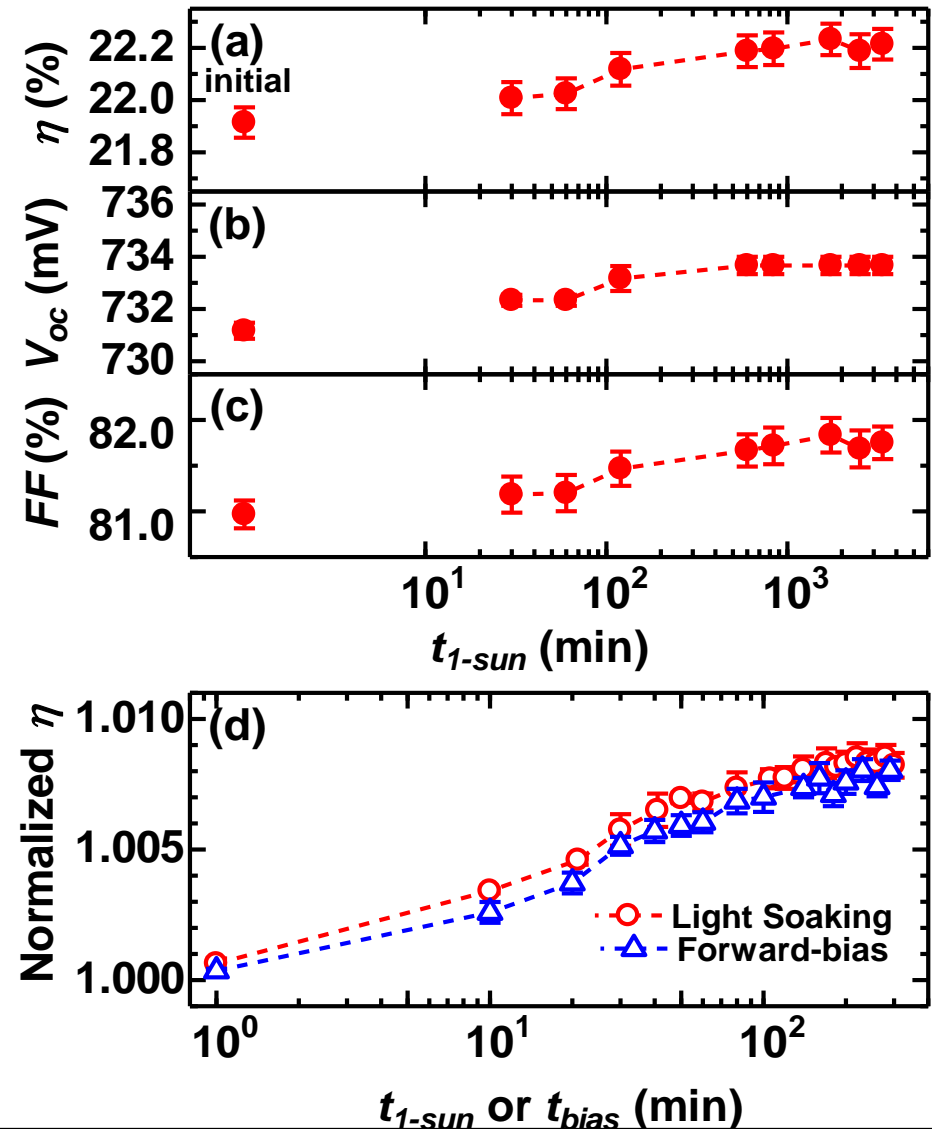
Kobayashi et al. APL 2016



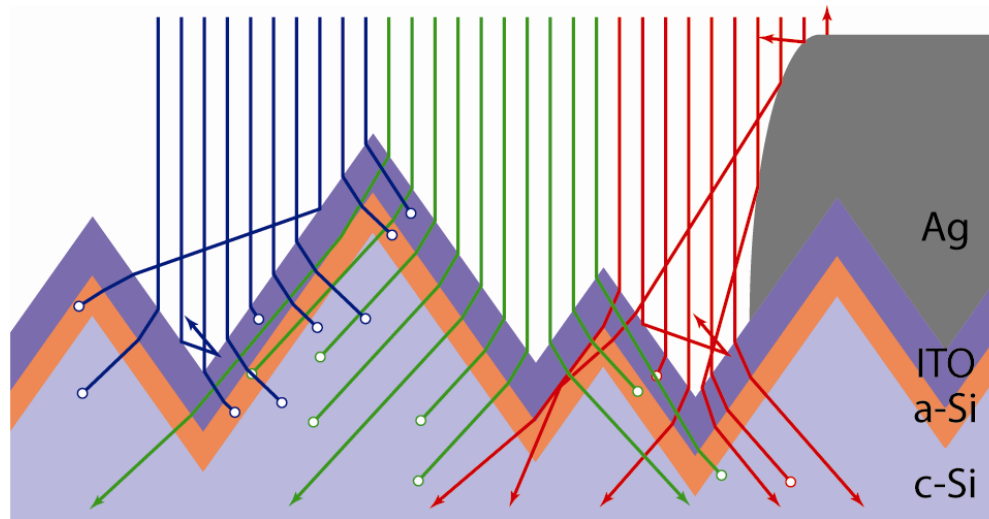
Lifetime increase with doped layers n and p layer !

Efficiency increase under light soaking

- SHJ efficiency increase under
 - light soaking or
 - recombination current
- Typically 1-1.5% relative increase !
- Still not fully understood...

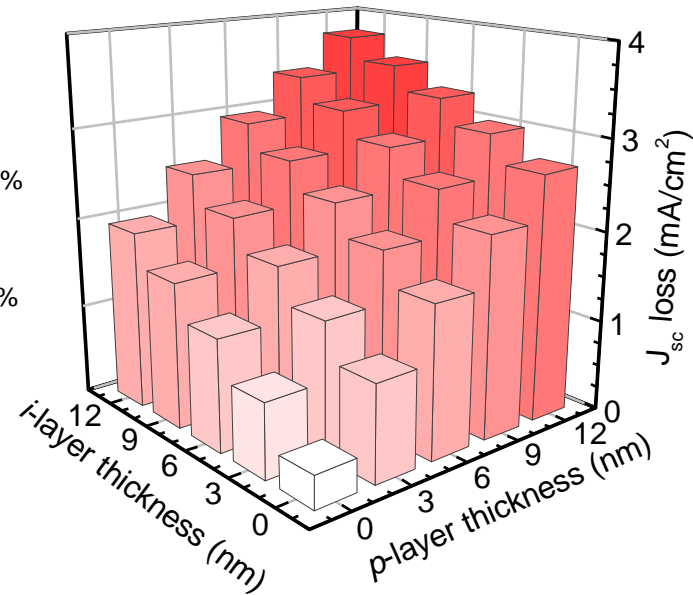
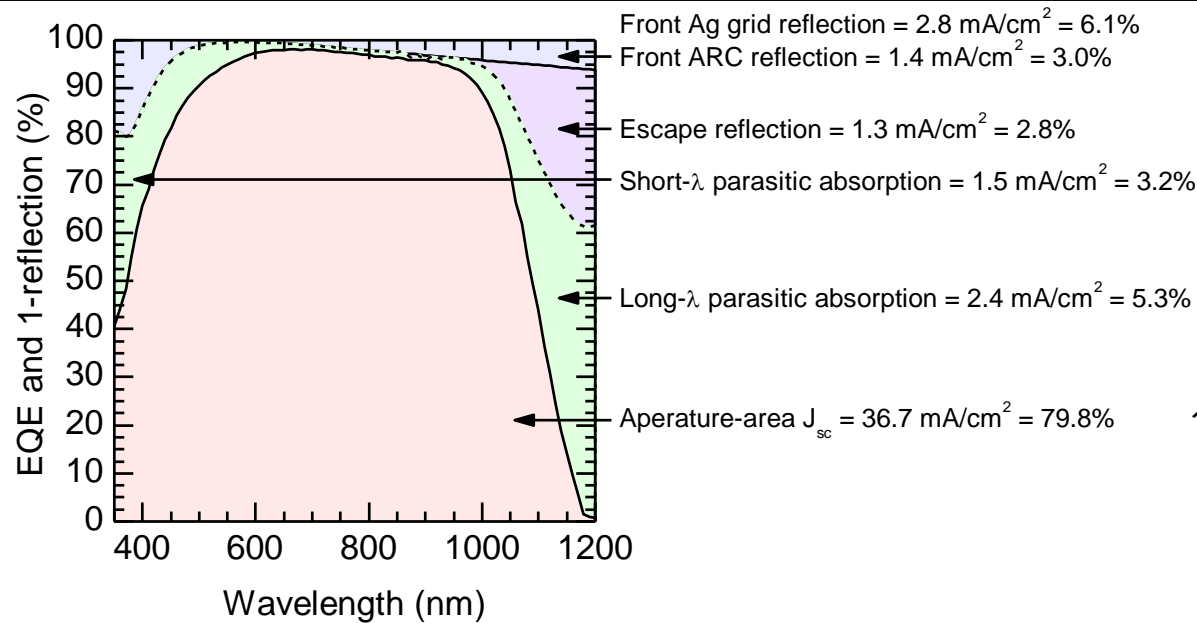


Light management



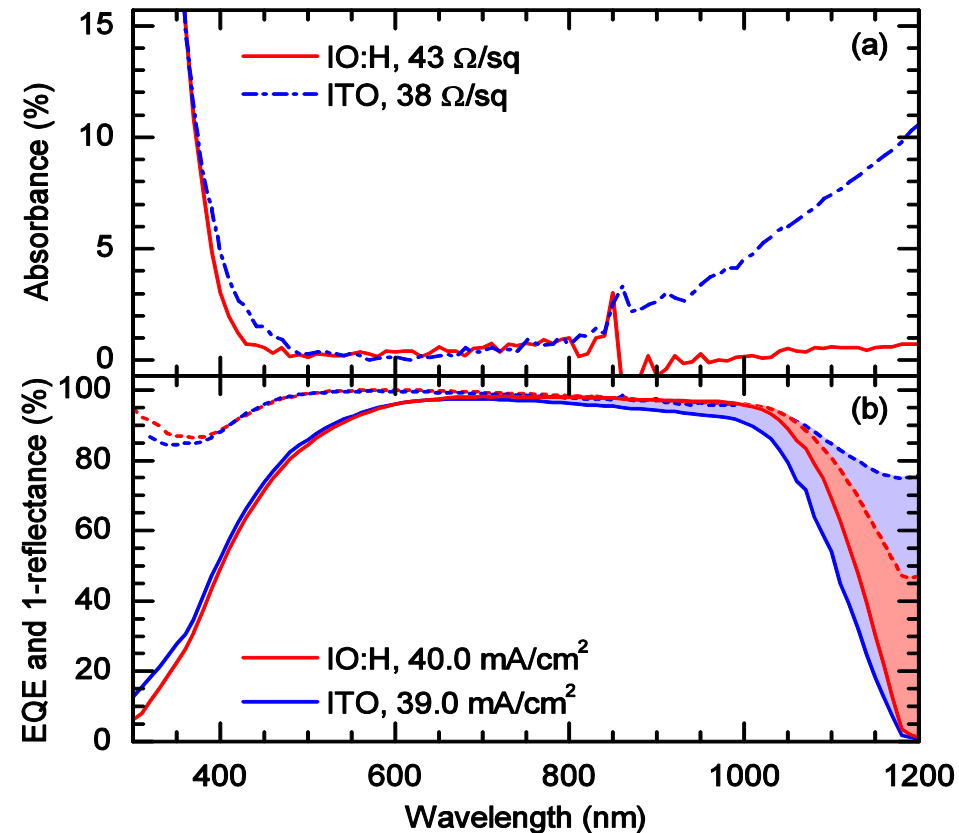
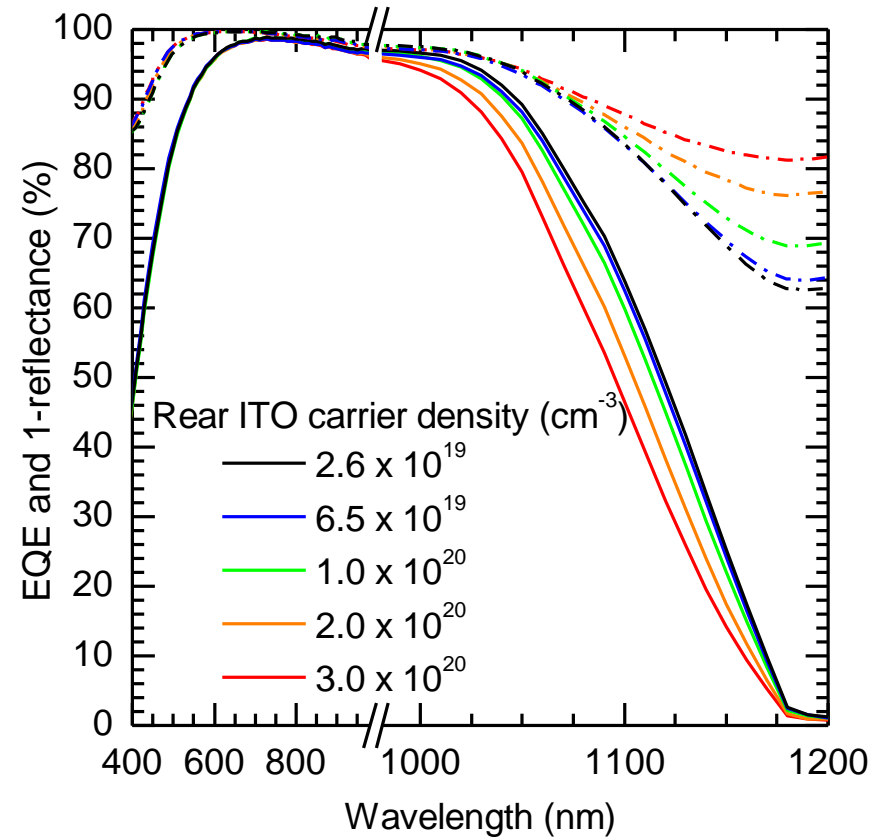
- Reflection from Ag grid and TCO anti-reflection coating
- UV and blue parasitic absorption in front *a*-Si layers
- UV and IR parasitic absorption in front TCO; IR parasitic absorption in rear TCO
- Incomplete trapping of IR light

Current losses at the front



- Over 2 mA/cm^2 is lost in an optimized heterojunction cell
 - due to parasitic absorption in the front layers
- All light absorbed in ITO and p -layer is lost, ~70% of light in i -layer is lost
- Model allows us to predict UV/blue current loss for arbitrary layers, provided optical constants are known

[Z. Holman *et al.*, IEEE JPV **2**, 7 (2012).]

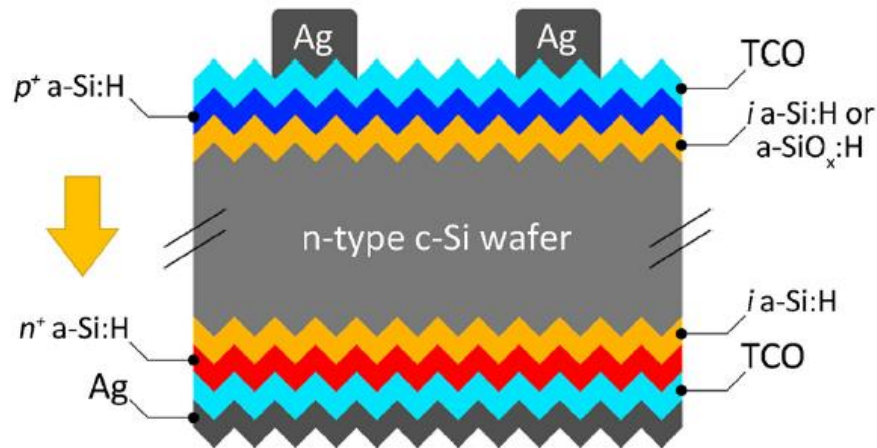


- Free-carrier absorption erodes J_{sc}
- Replace ITO with IO:H or other high mobility TCO

[T. Koida *et al*, JJAP (2008);
L. Barraud *et al.*, SOLMAT (2013).]

Reduction of parasitic absorption through single-, mixed-phase and alloyed materials: microstructure and band gap variation

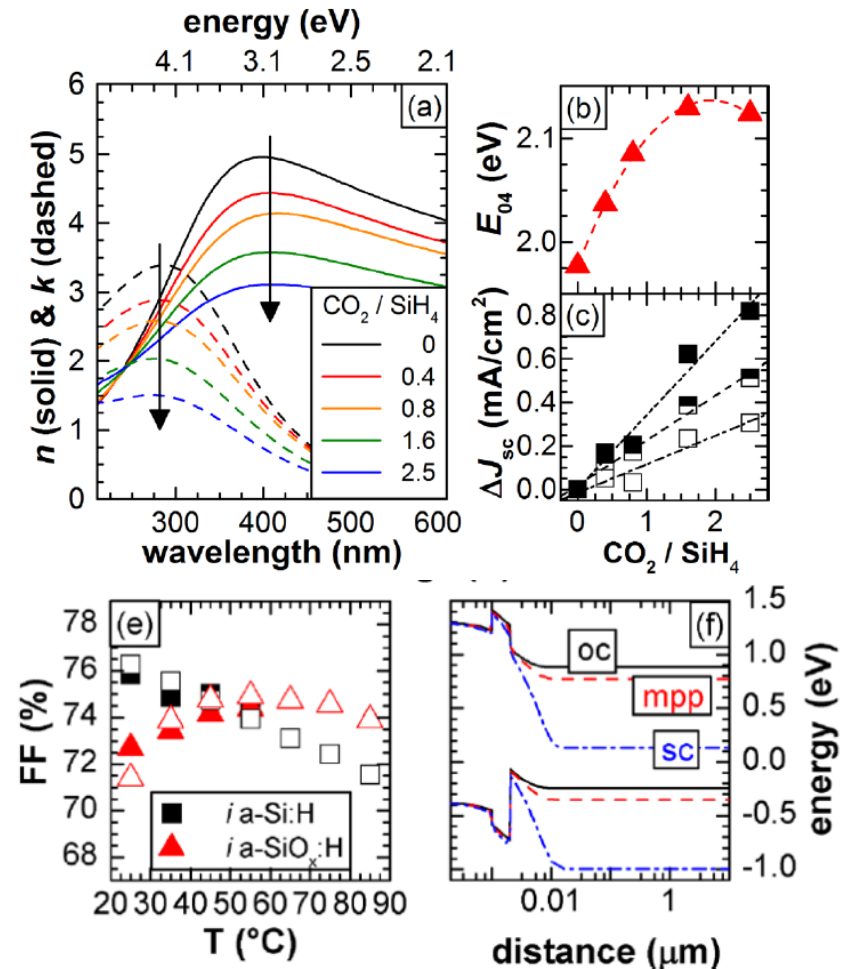
➤ (i)a-SiO:H



➤ Doped μ c-Si:H

➤ Doped and intrinsic μ c-SiO_x:H and a-SiO_x:H

➤ Doped a-SiC:H

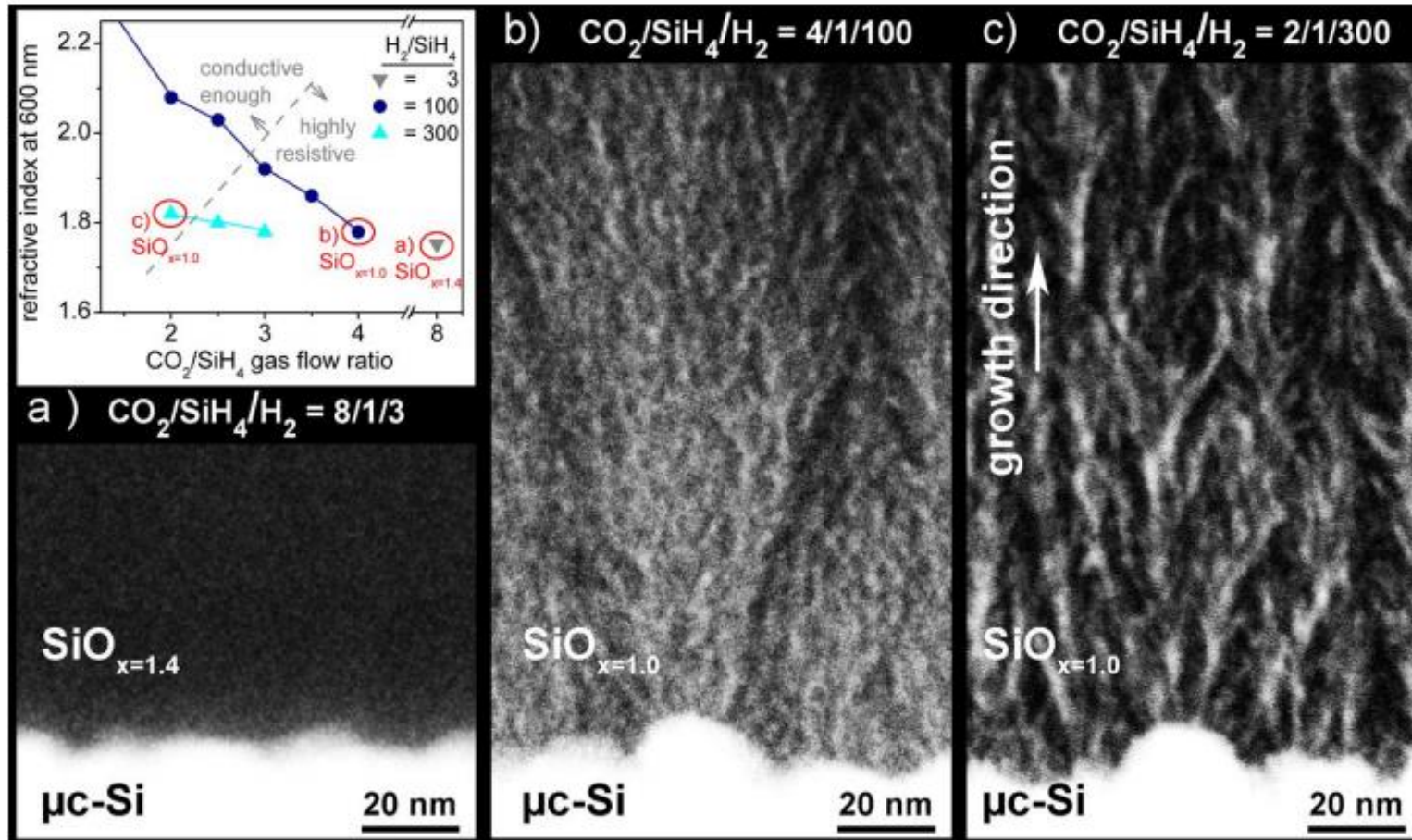


[Seif et al., Mazzarella et al., Van Cleef et al....]

[J.P. Seif *et al.*, JAP **115**, 024502 (2014).]

Current losses at the front

Nano-crystalline SiO layers

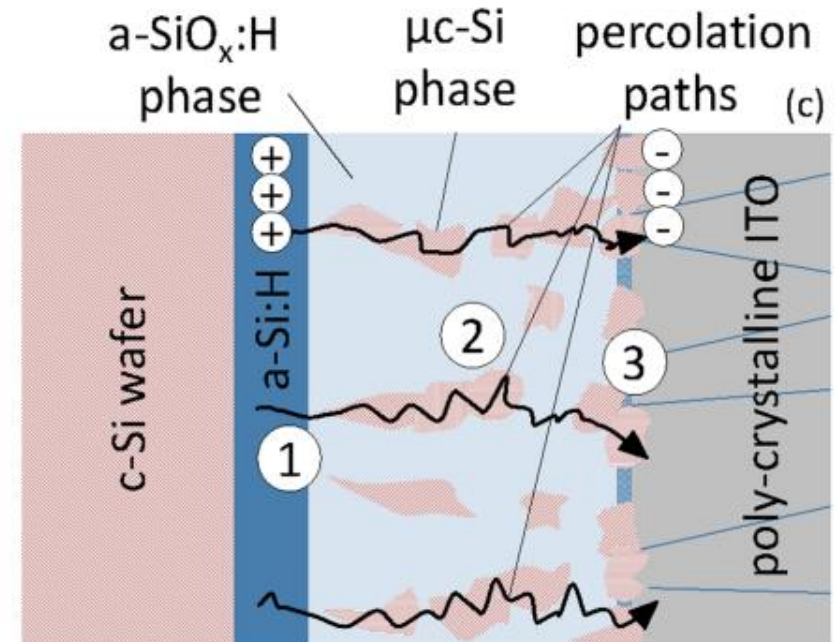
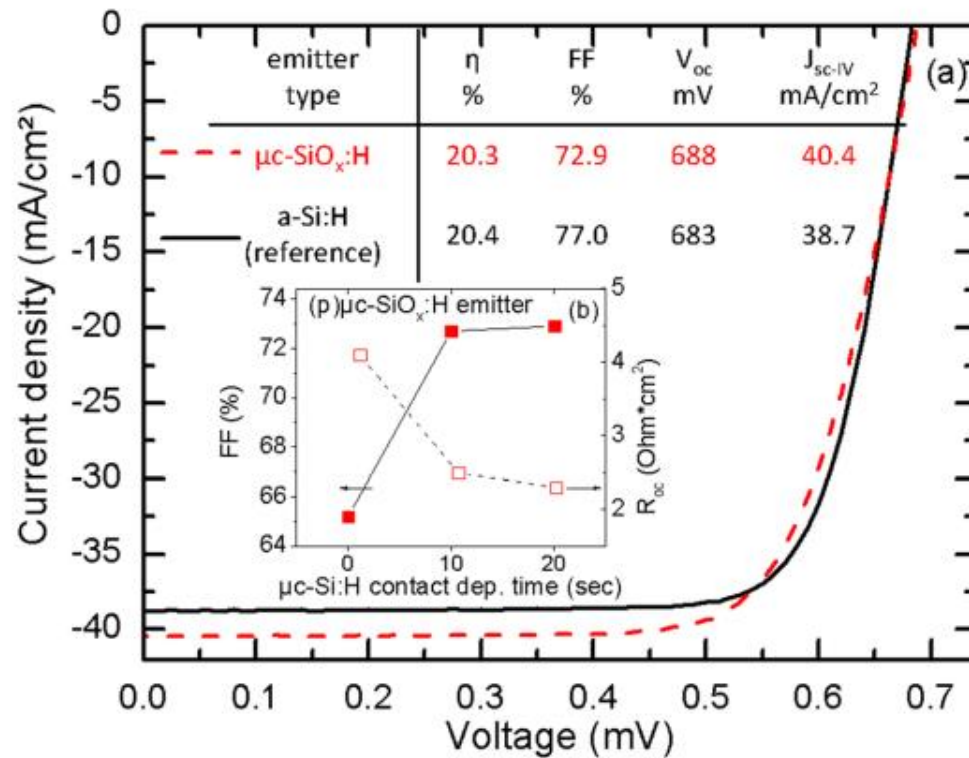


[Kaneka patent !]

[P. Cuony, PhD thesis, EPFL, 2010]

Current losses at the front

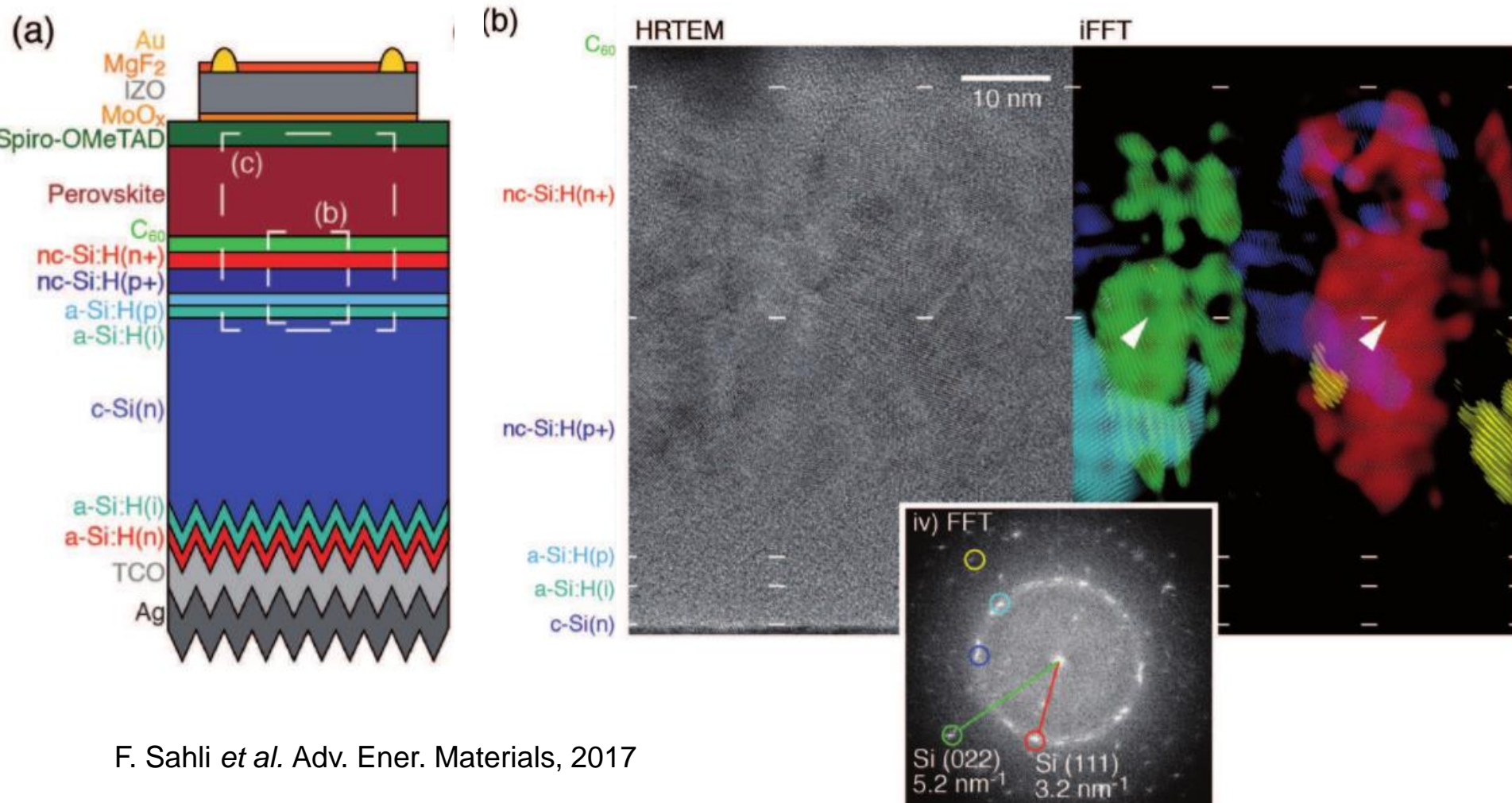
Nano-crystalline SiO layers



Jsc gain but FF drop...

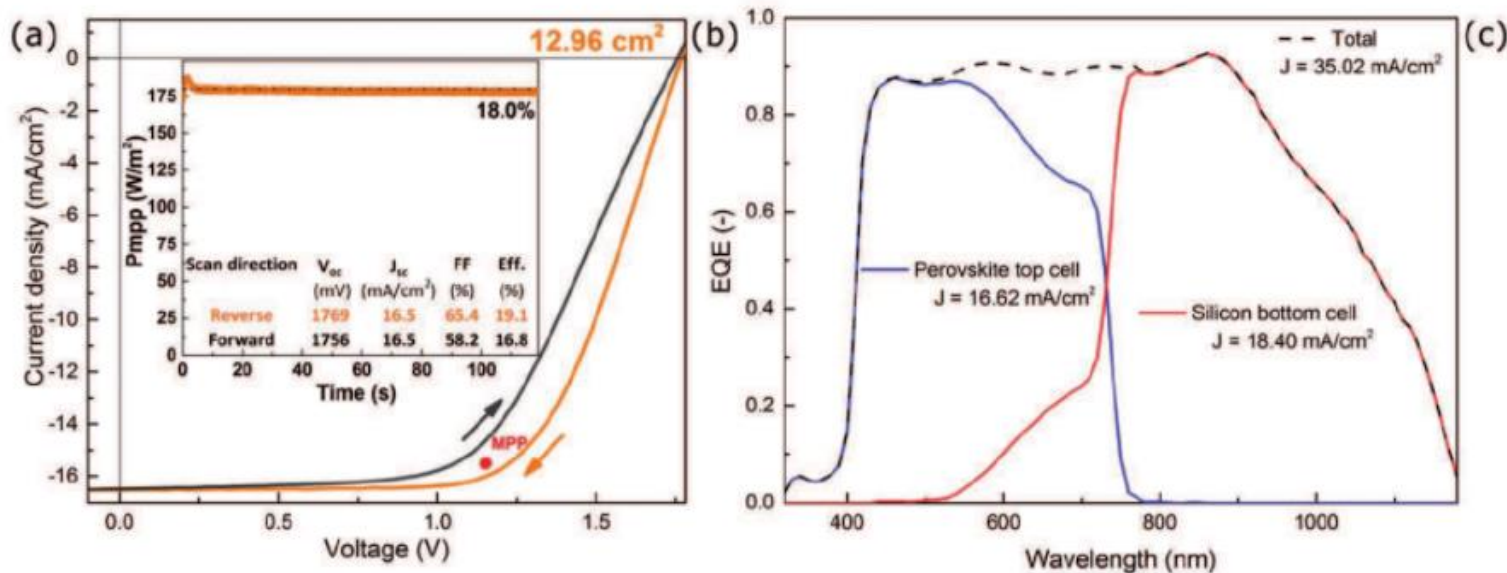
[L. Mazzarella, APL106, 023902 (2015)]

- Preventing the need for transparent window contact: Tandems!



F. Sahli *et al.* Adv. Ener. Materials, 2017

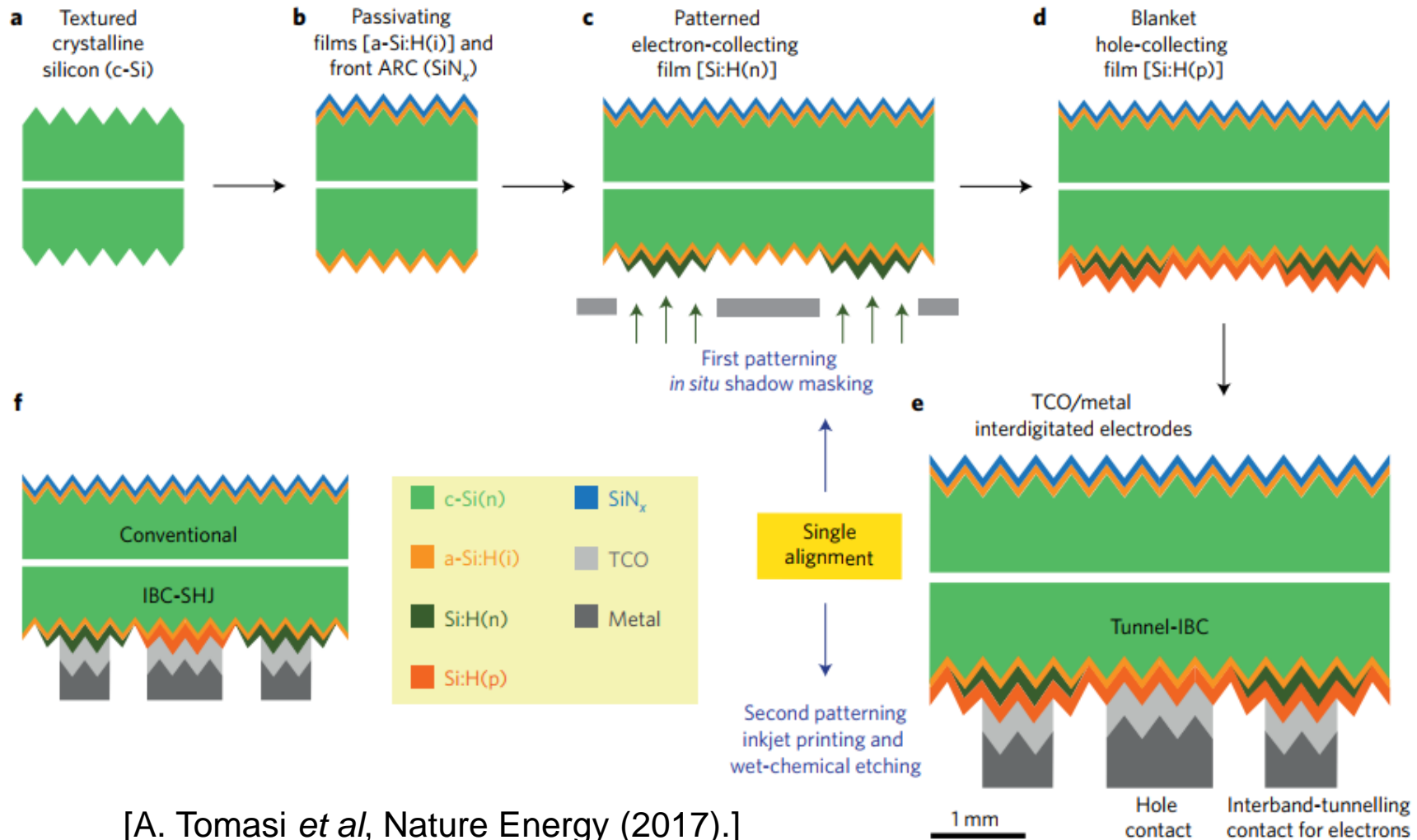
- Preventing the need for transparent window contact: Tandems!
 - Lower shunting → easier large-area integration
 - better optical coupling → higher photocurrents



F. Sahli *et al.* Adv. Ener. Materials, 2017

Current losses at the front

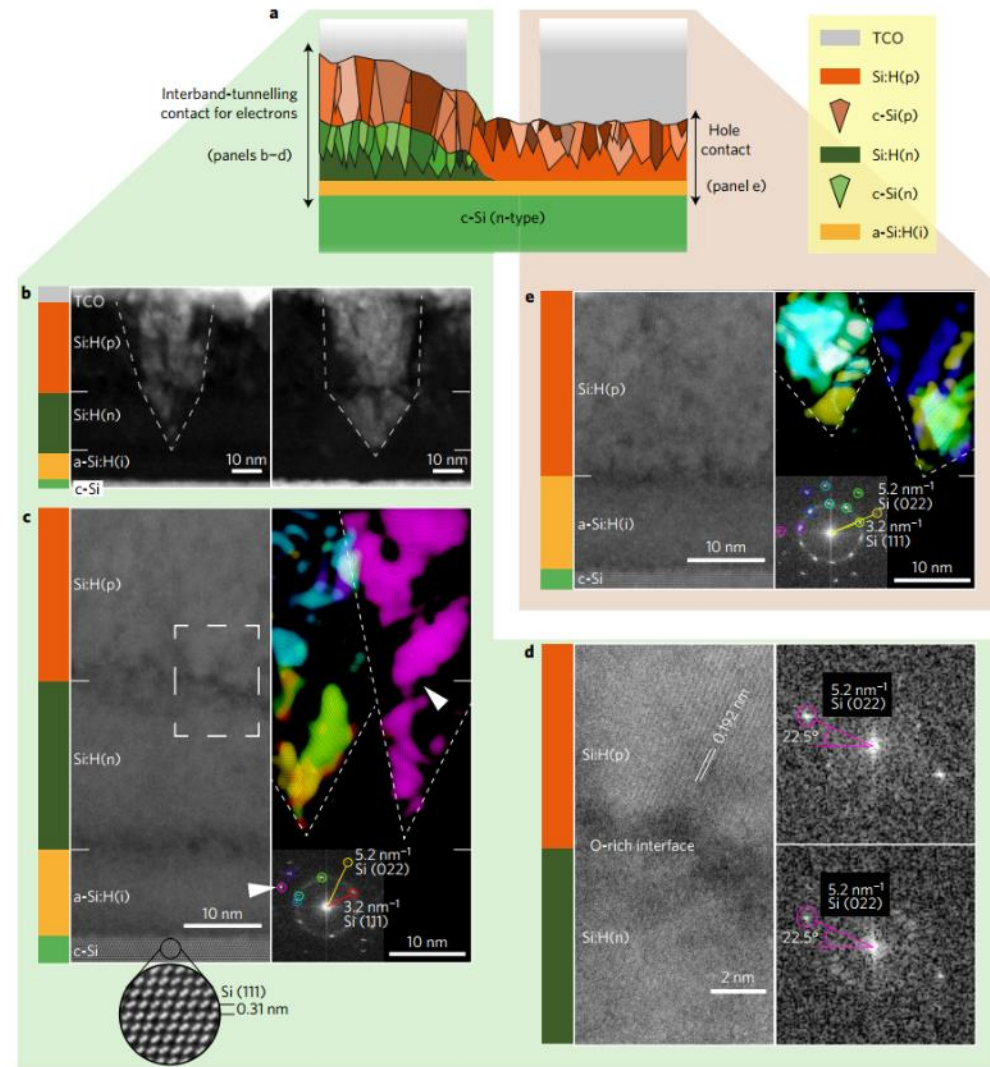
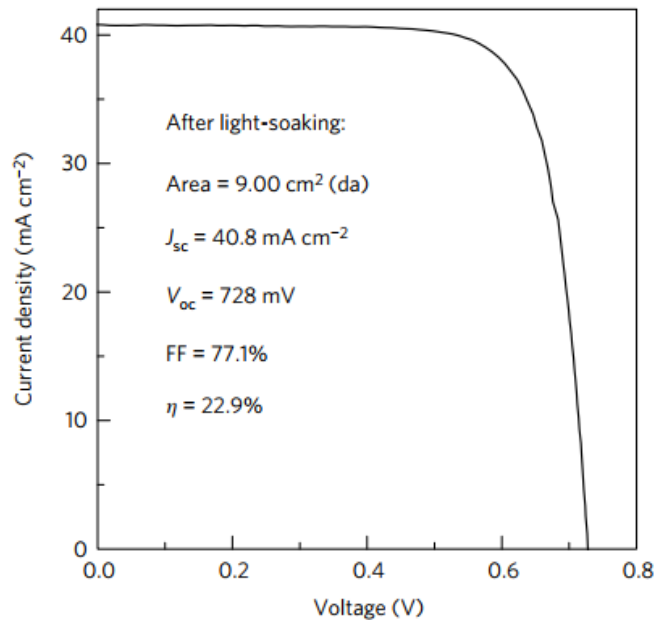
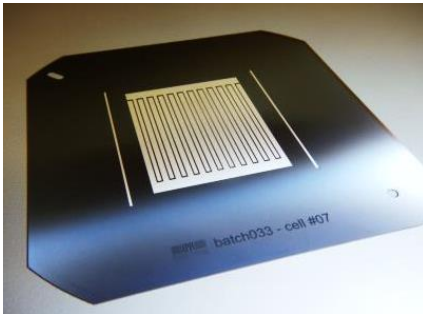
- Preventing the need for transparent window contact: IBC !



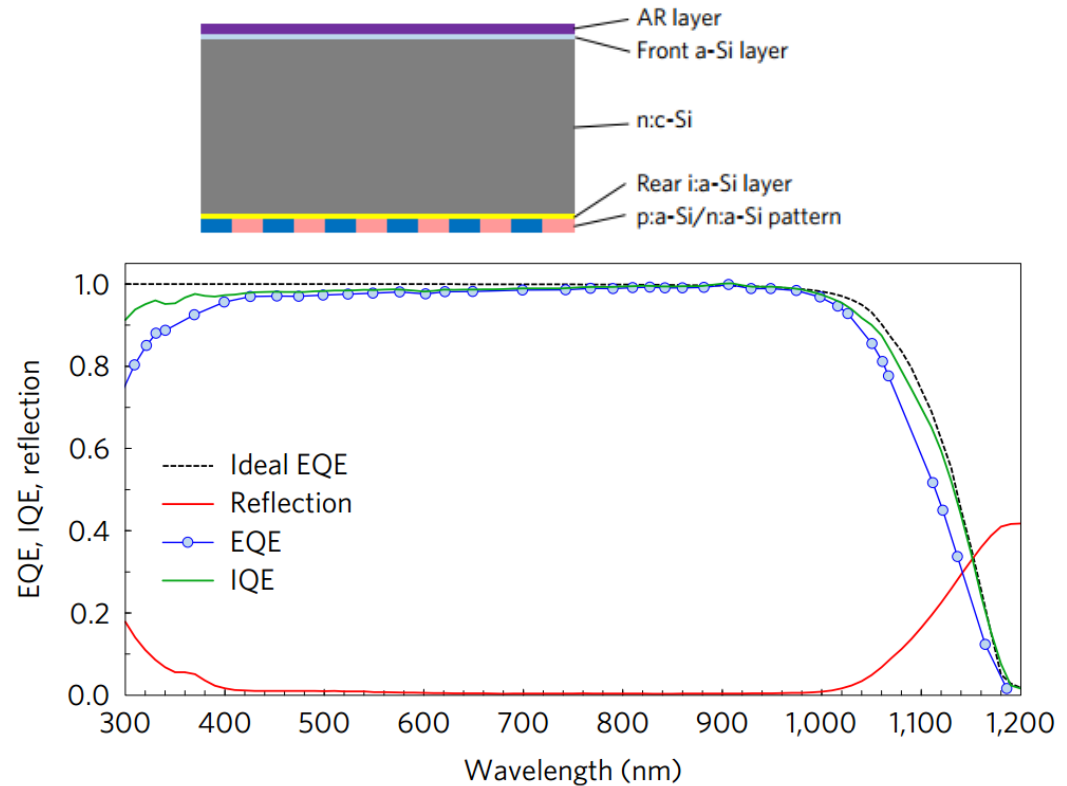
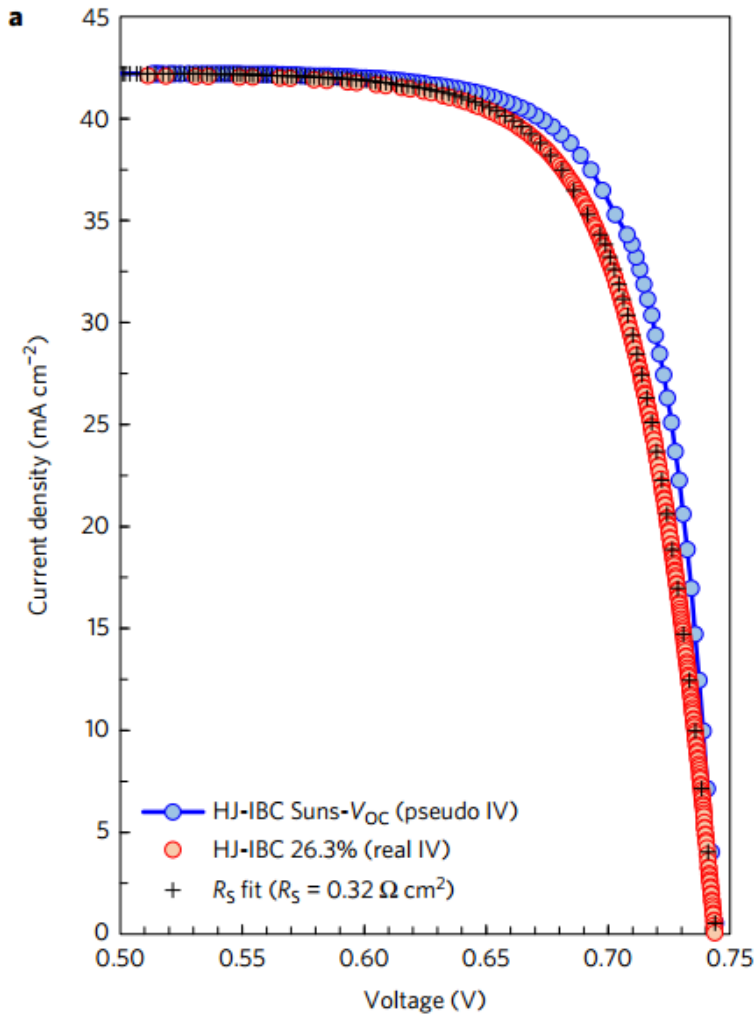
[A. Tomasi *et al*, Nature Energy (2017).]

Current losses at the front

Fully back contacted solar cells



[A. Tomasi *et al*, Nature Energy (2017).]



Optimized process
→ Ultra-low R_s and optical losses

[Yoshikawa *et al*, Nature Energy (2017).]

Conclusion and perspective

Old / New technology

- 25 years from invention to large-area world record / module efficiency world record
- Tremendous TF-Si knowledge as background
- Good perspectives for large-scale production ?

Delicate process

- “Secret” to high FF mastered by a couple of (Japanese) companies...
- Good passivation for thin layers requires lots of know-how
- Still many open questions on the physics of passivation

Opportunities

- Lots of knowledge on contacts to gather for all PV technologies
- There **must be** better alternative contacts to a-Si:H

Acknowledgement for funding

- Swiss National Science Foundation ICONS award
- EC Horizon 2020 projects NextBase, Disc and Ampere



